

# Visualization Tools

Ricardo Reis, Mateus Fogaça, Guilherme Flach

# Where

# do we come from ...



Porto Alegre

# Where do we come from



# Porto Alegre





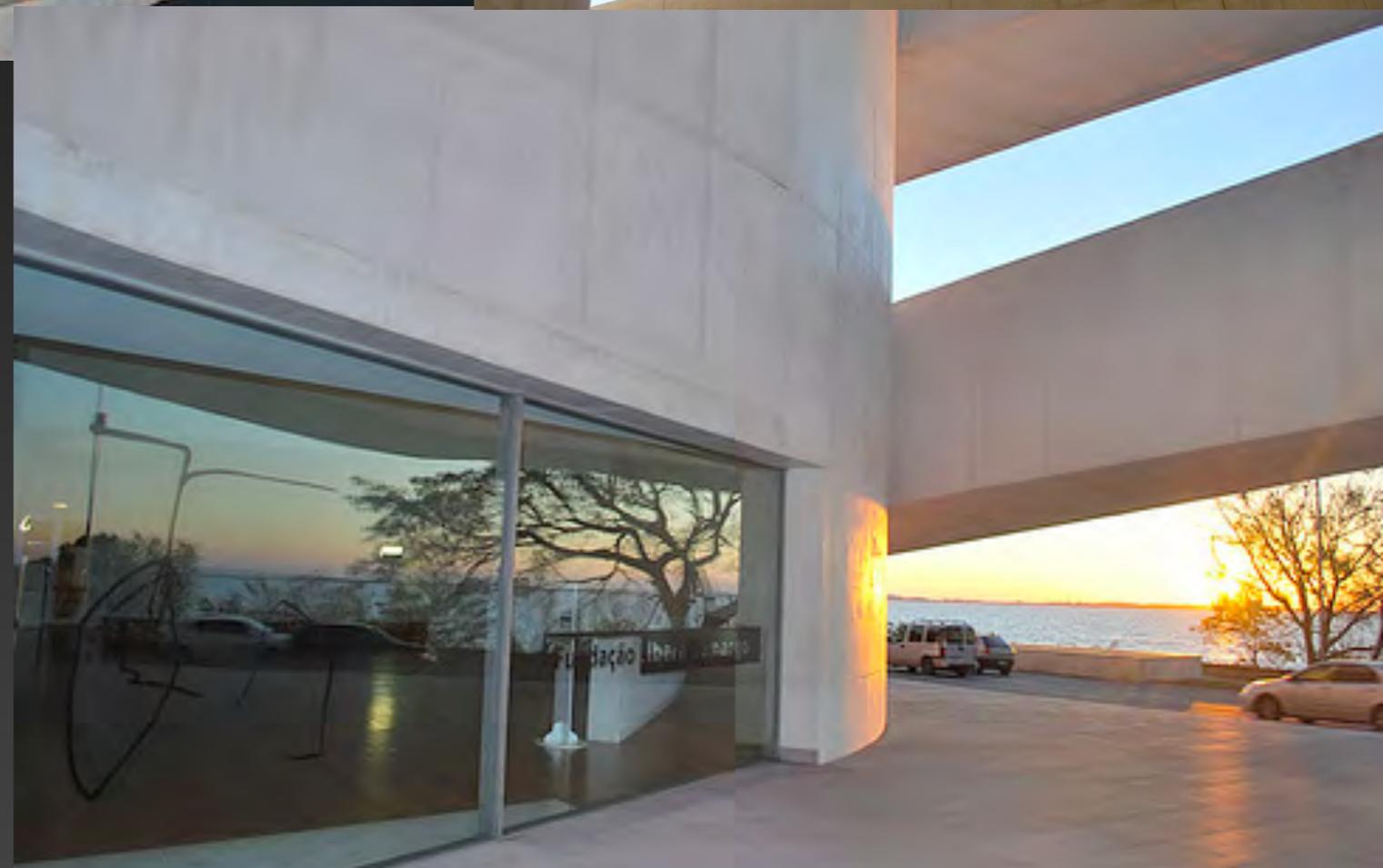
# Porto Alegre





Iberê Camargo  
Museum

Porto Alegre





# Instituto de Informática



# CEITEC



**Design Center - Administrative Building:**

**Design Center  
Process Engineering  
Adm. Offices  
Teaching Rooms  
Auditorium  
5.100 m<sup>2</sup>**

**Manufacturing Building**

**Manufacturing Cleanroom  
Research & Development  
Cleanroom  
Facilities and Support  
9.600 m<sup>2</sup>**

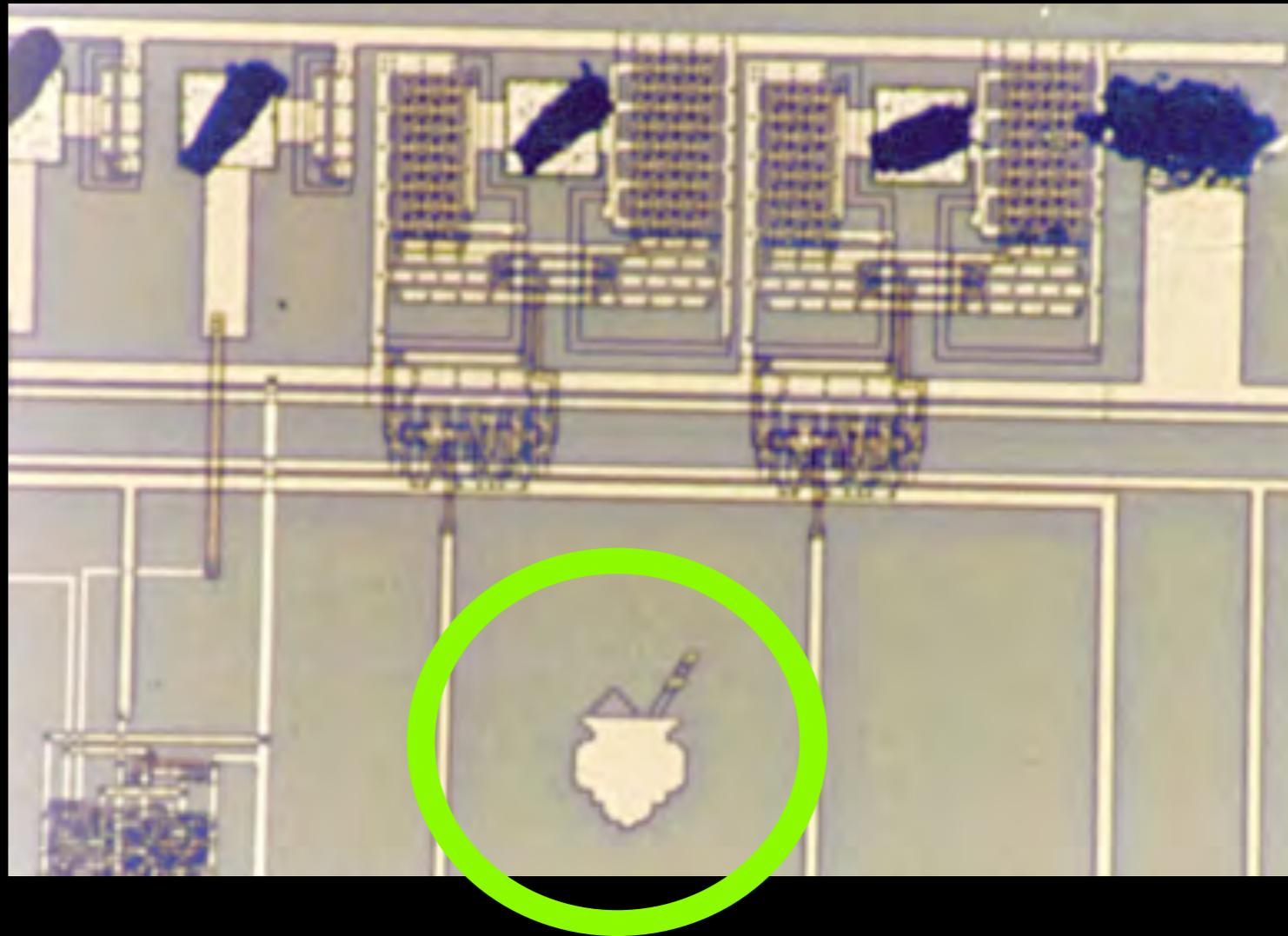
4.000 wafers/month (200 a 15.000 chips/ wafers)

# CEITEC



# A bit of History

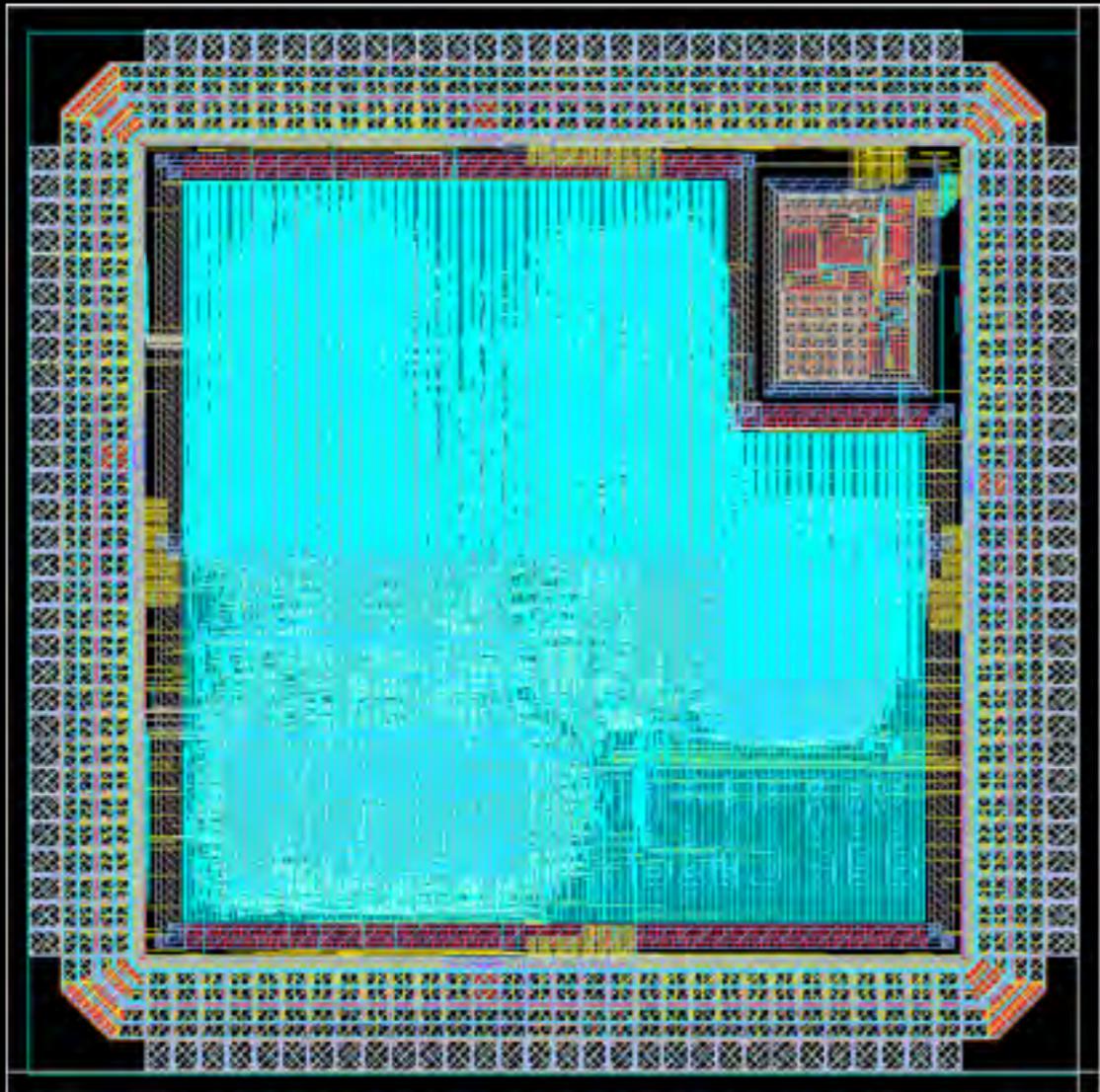
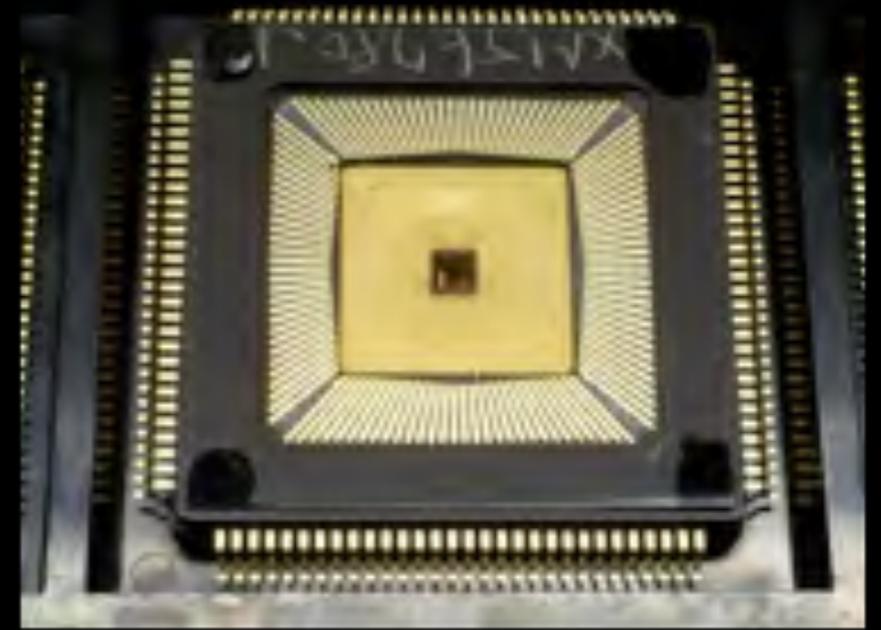
1984 – Access to MPW prototyping (fabricated at ES2, France)



1986 – RISCO 16b/32b completed  
First RISC Microprocessor in Brazil (Architecture to Layout)

2012

# TMR MIPS Duo Core 32 bits chip tolerant radiation effects



see more at: <http://www.nscad.org.br/site/nsc21101>

# Microelectronics Group Research Topics

Embedded Systems

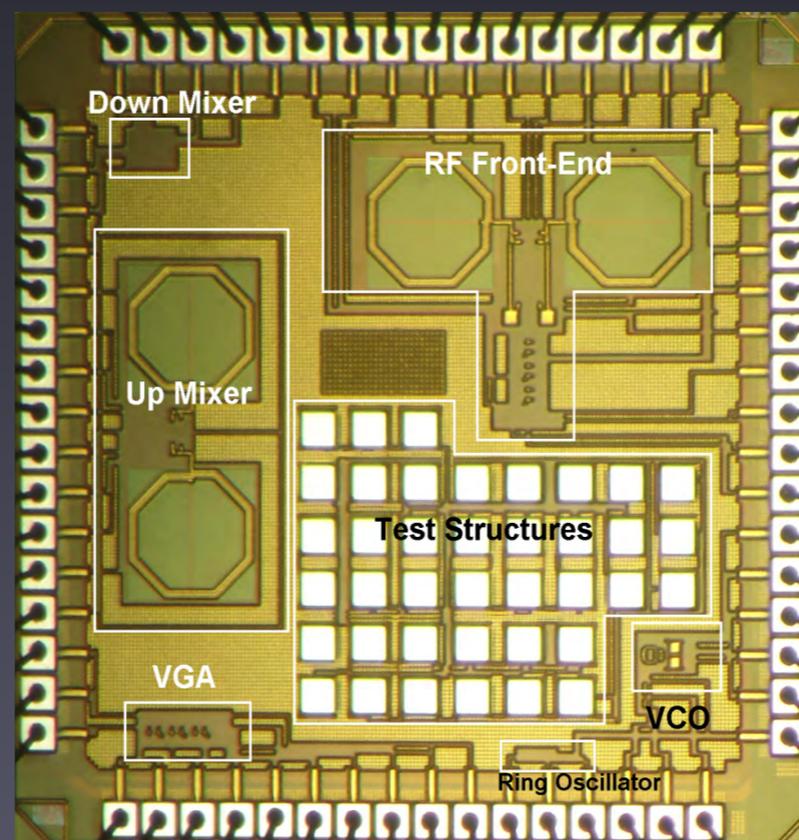
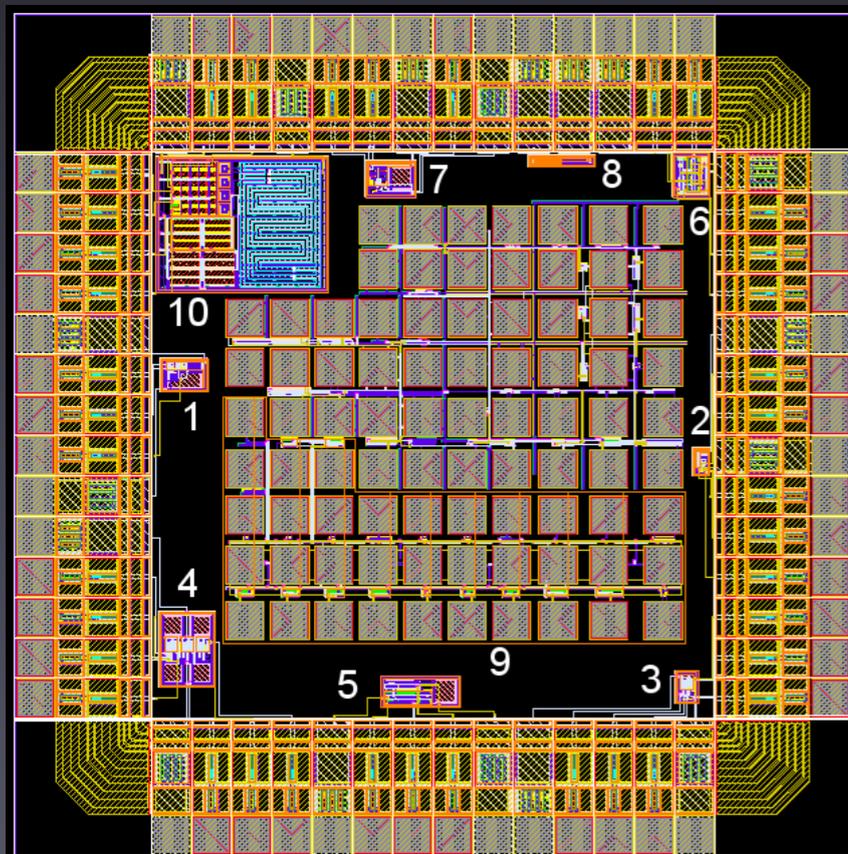
Analog Design

Digital Design

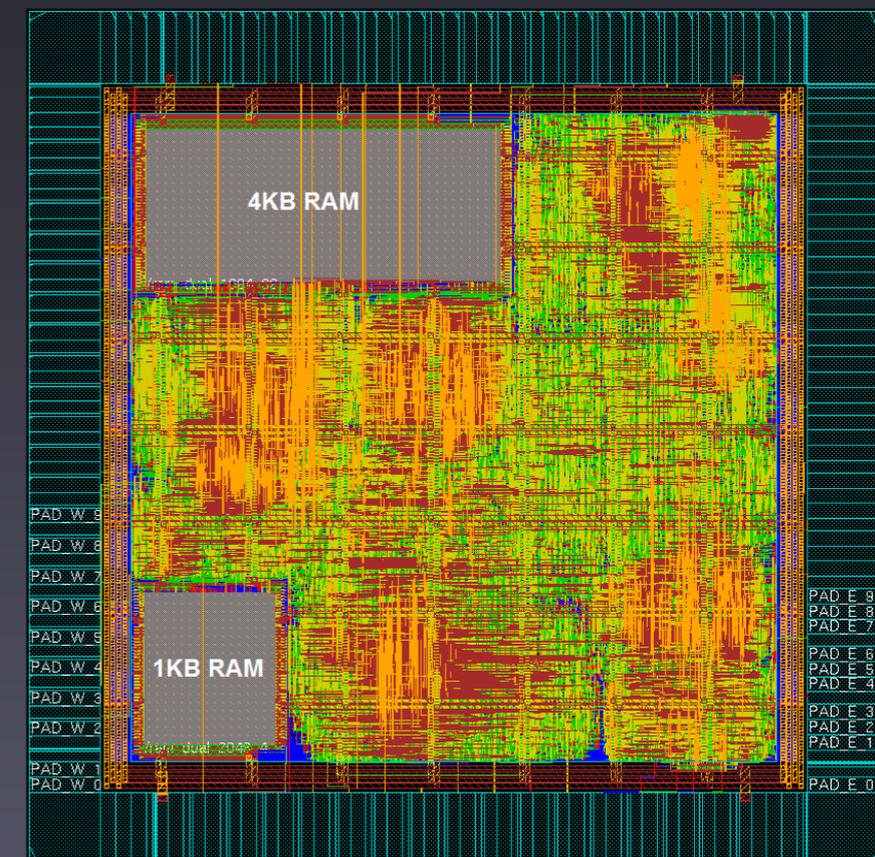
Design Methodologies

VLSI Architectures and Dedicated Architectures

Digital TV



A Multi-Band RF Front End interface



A block of the video decoder

# Microelectronics Group Research Topics

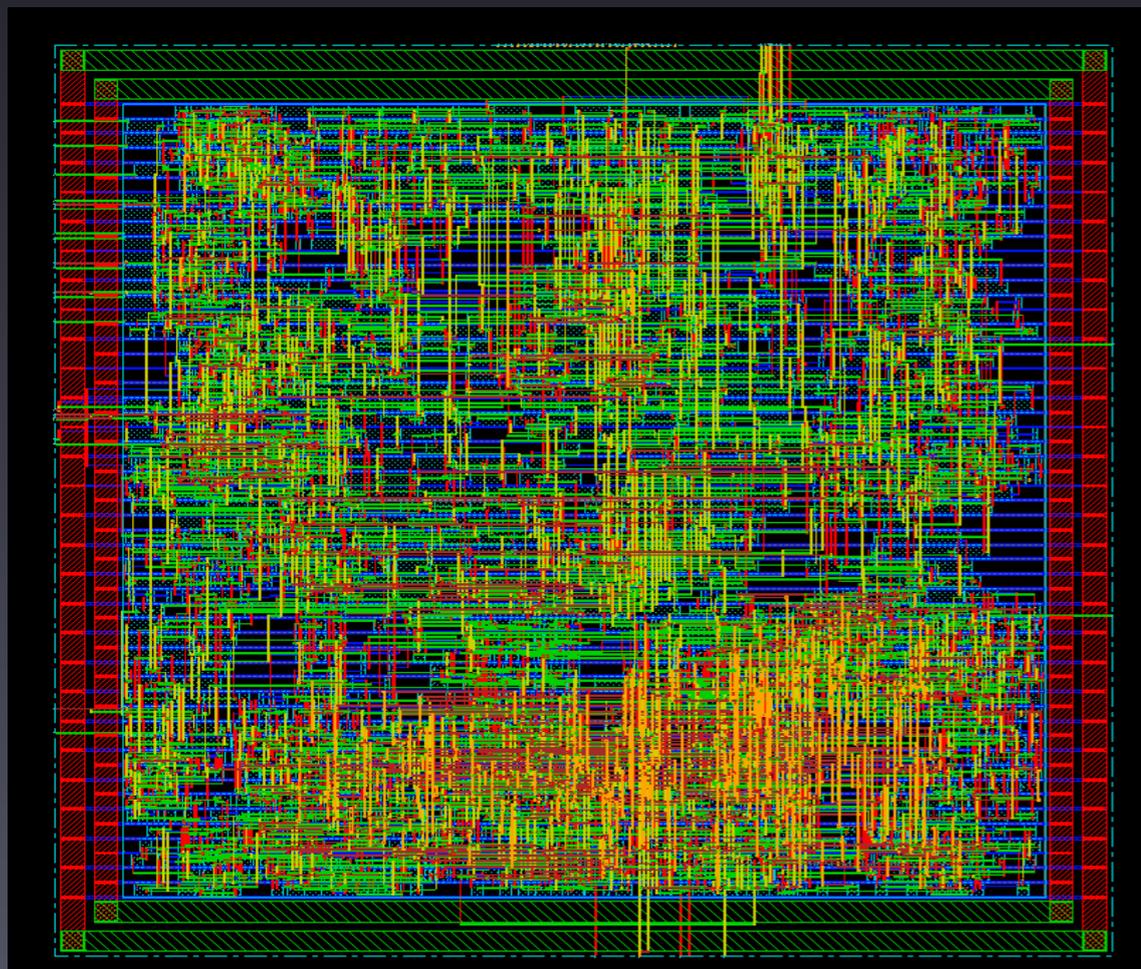
**SoC - Systems on a Chip**

**NoC - Networks on Chip**

**MEMs**

**DSP Systems (video, voice, image)**

**FPGA Design Methodologies**



ASIC - CA-VL Coding module  
CABAC coder/decoder - Parser



FPGA H.264 Coder prototyping

# Microelectronics Group Research Topics

Fault Tolerant Circuits

Circuits Tolerant to Radiation Effects

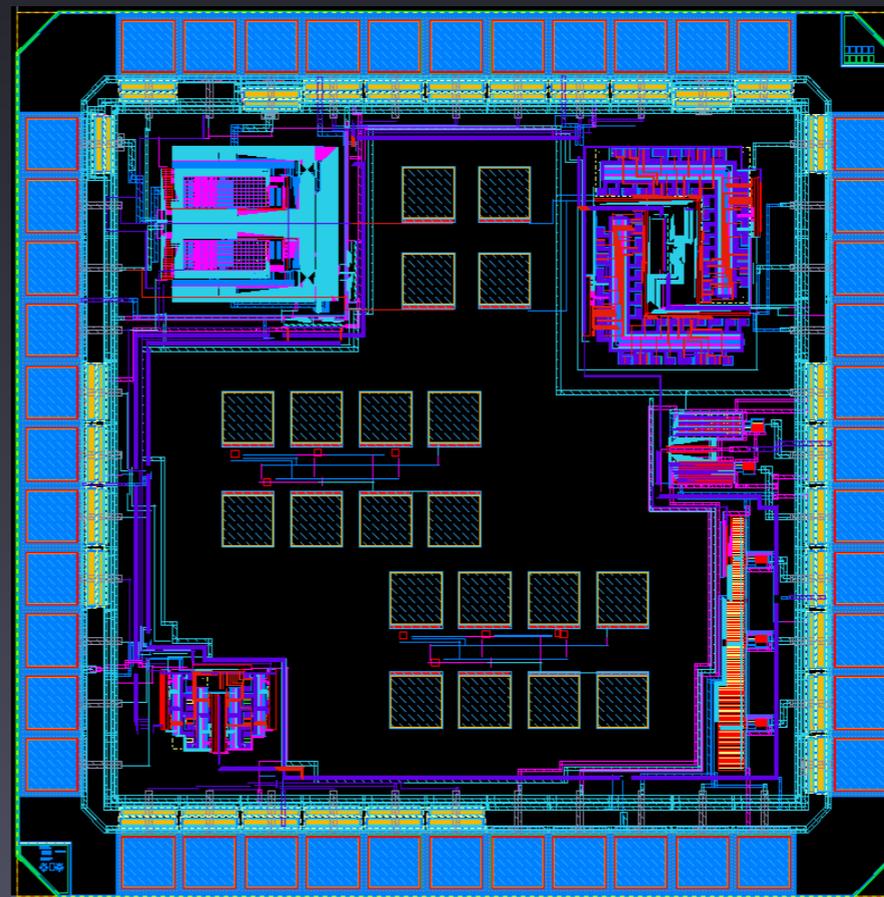
Variability

Test

Mixed Signal

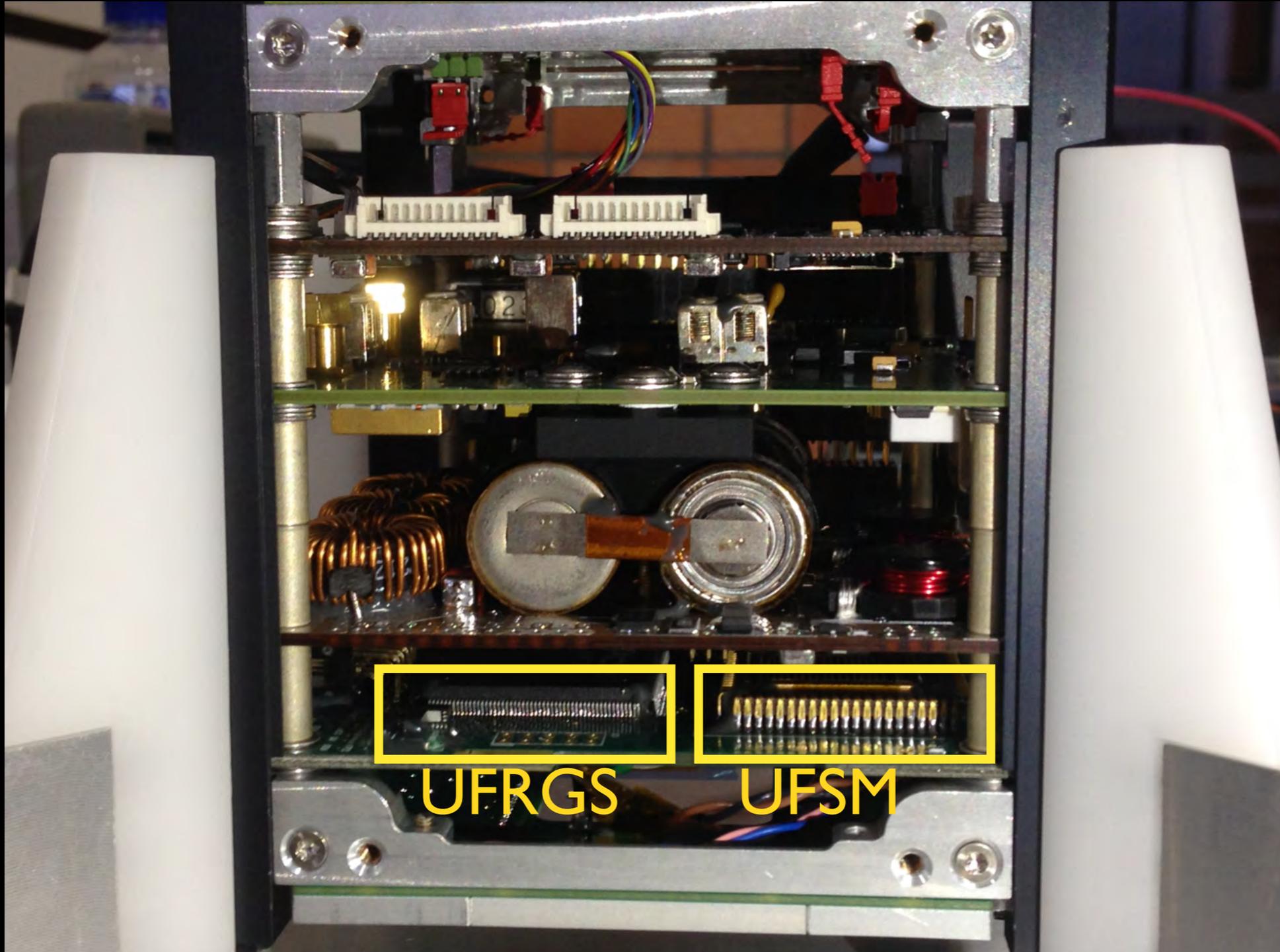


Electrical testing of RFID 915MHz  
(CEITEC Design)



65nm CMOS Variability test structures

# NanoSatC-BR I



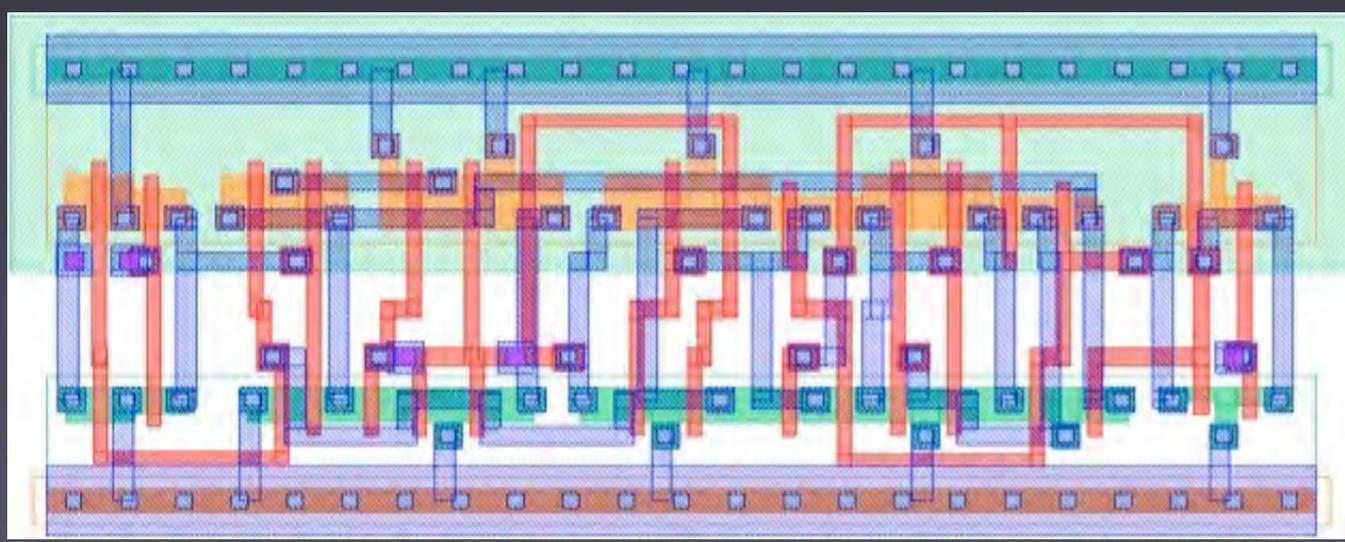
# Microelectronics Group Research Topics

Logic Synthesis

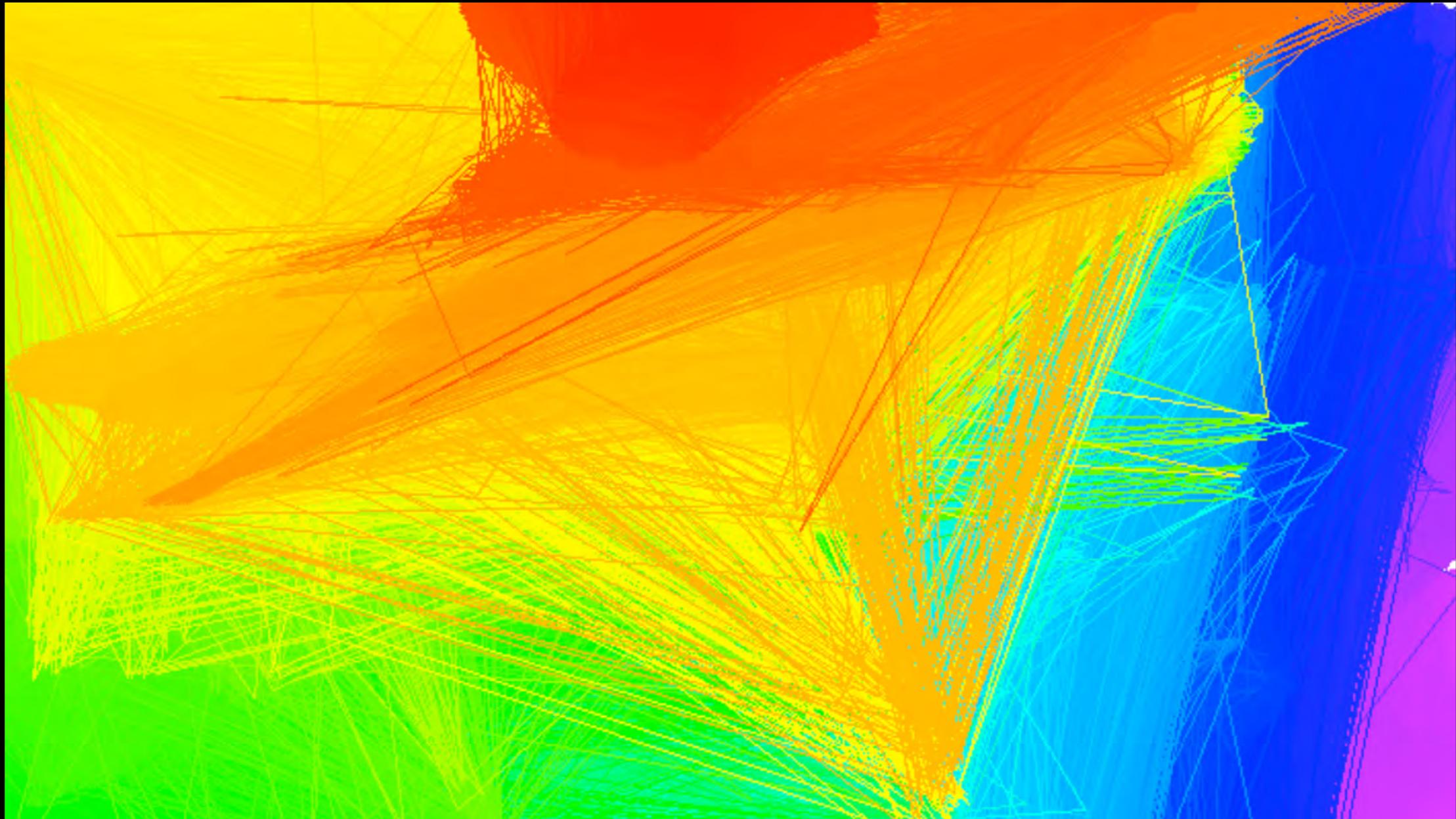
Physical Design

Design of Transistor Networks

EDA Tools



Designed Automatically with ASTRAN



# Visualization Tools

Ricardo Reis, Mateus Fogaça, Guilherme Flach

# A bit of History

# Visualization of Working Chips using E-Beam Microscope

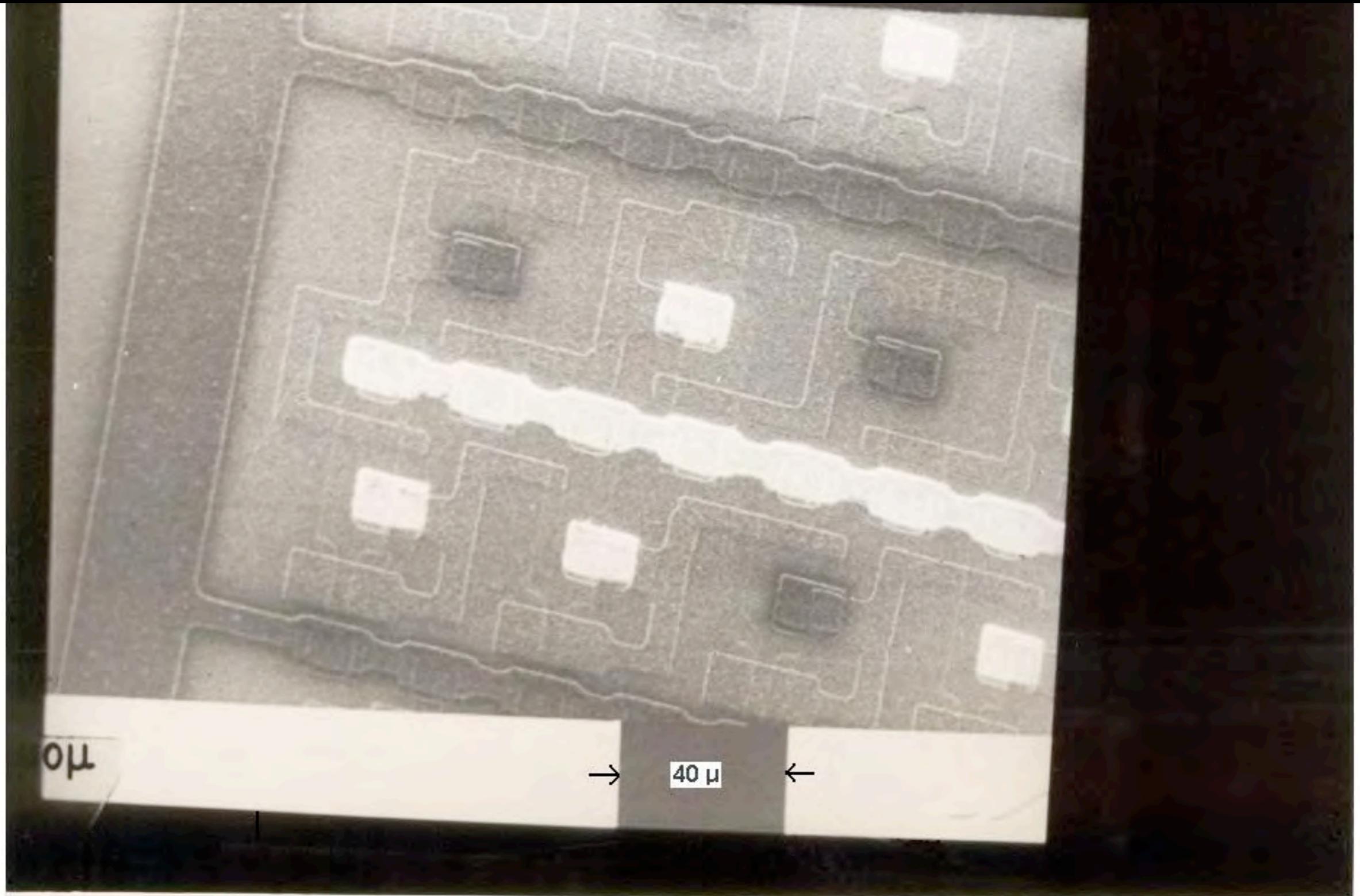
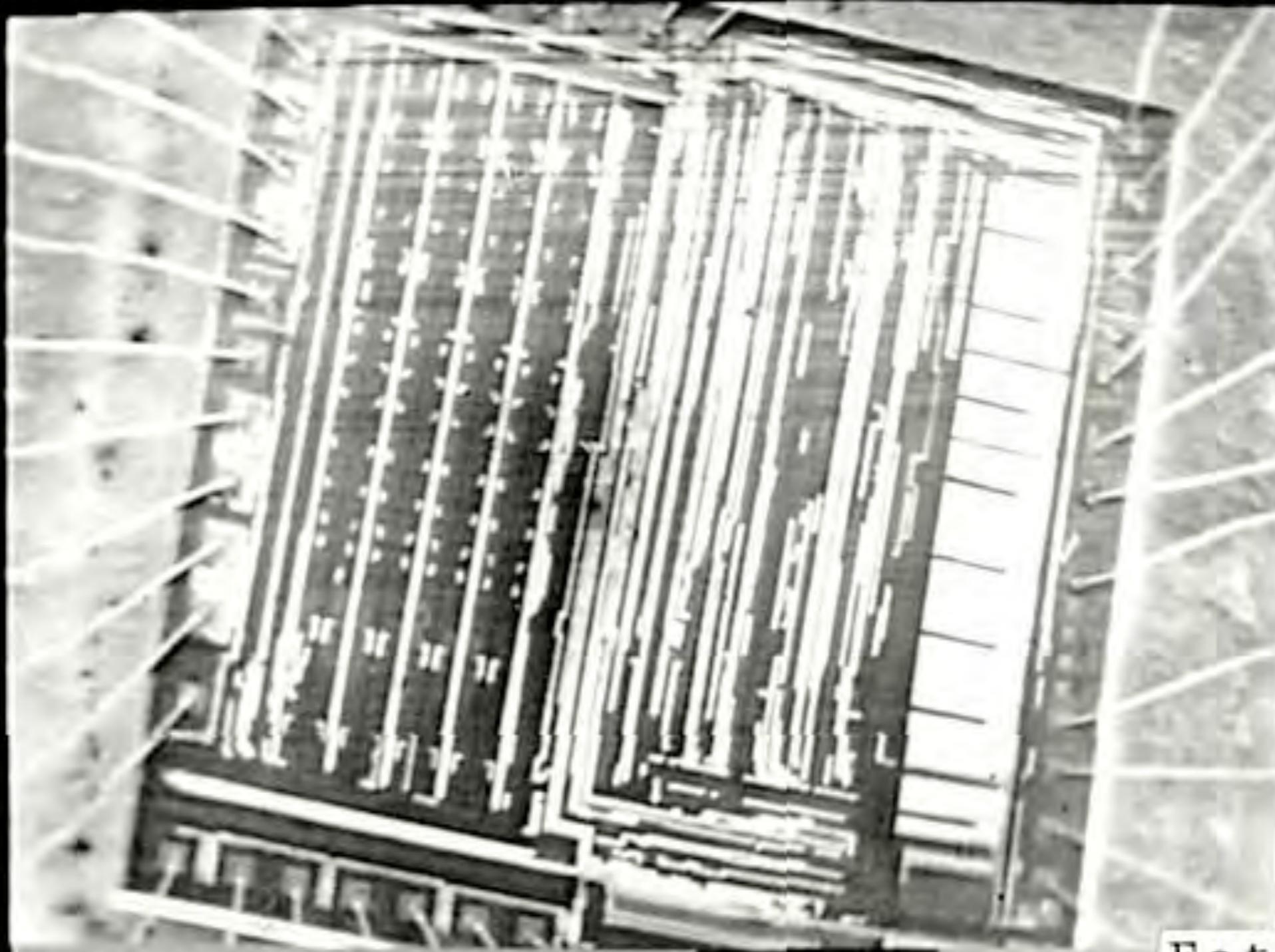


Image from Voltage Contrast (A= x500, E = 40 μm)

Carlos Hurtado UFRGS 1986

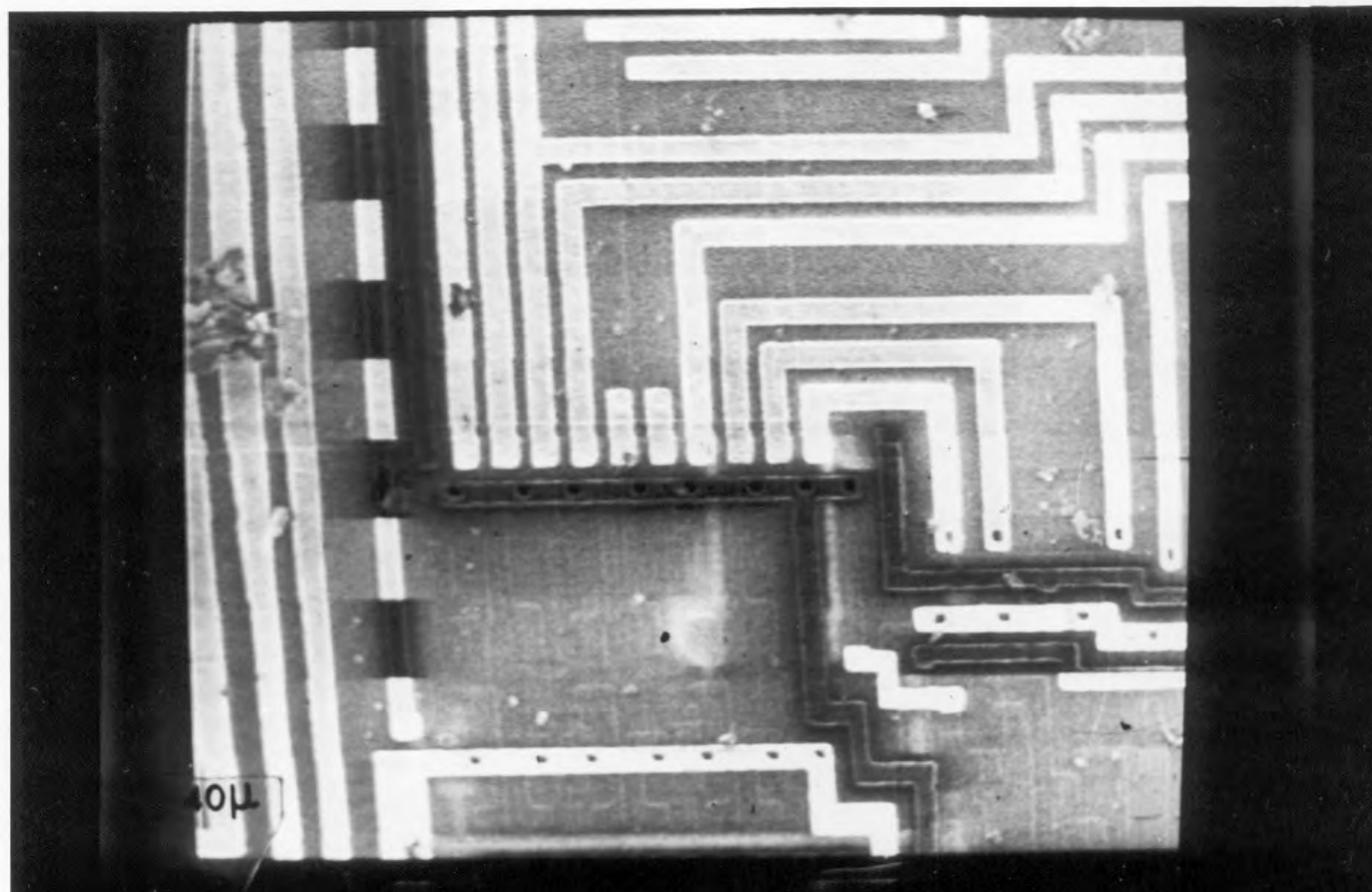
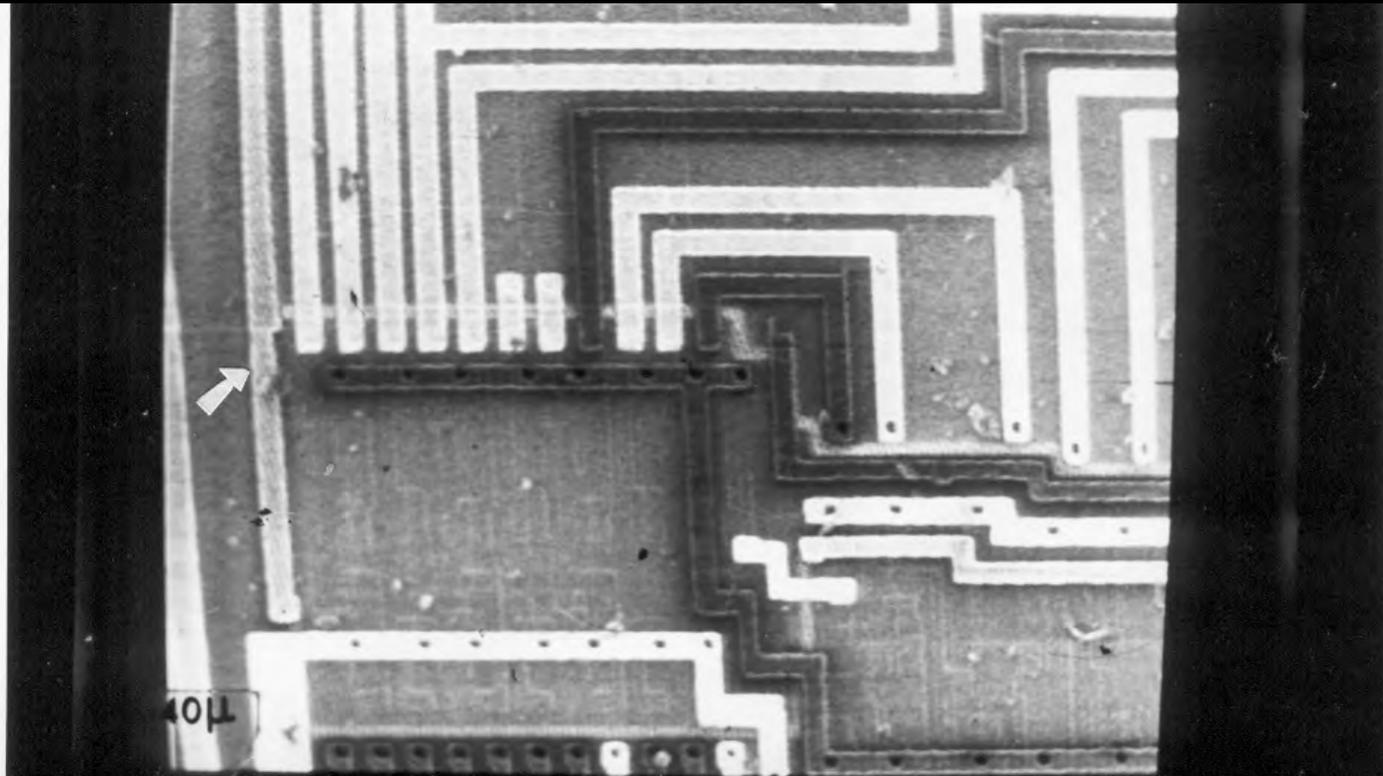
# Visualization of Working Chips using E-Beam Microscope



IMM

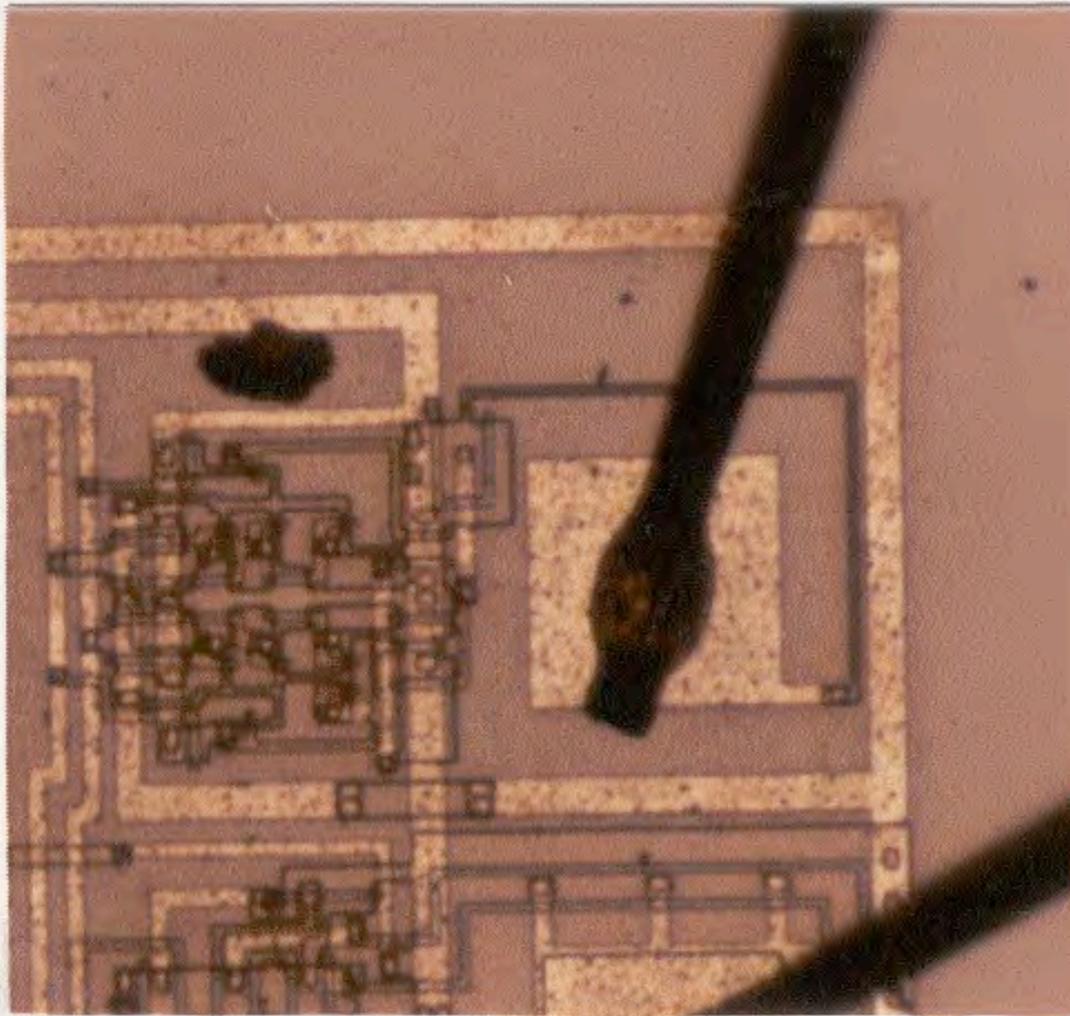
Foto Zim

# Visualization of Working Chips using E-Beam Microscope

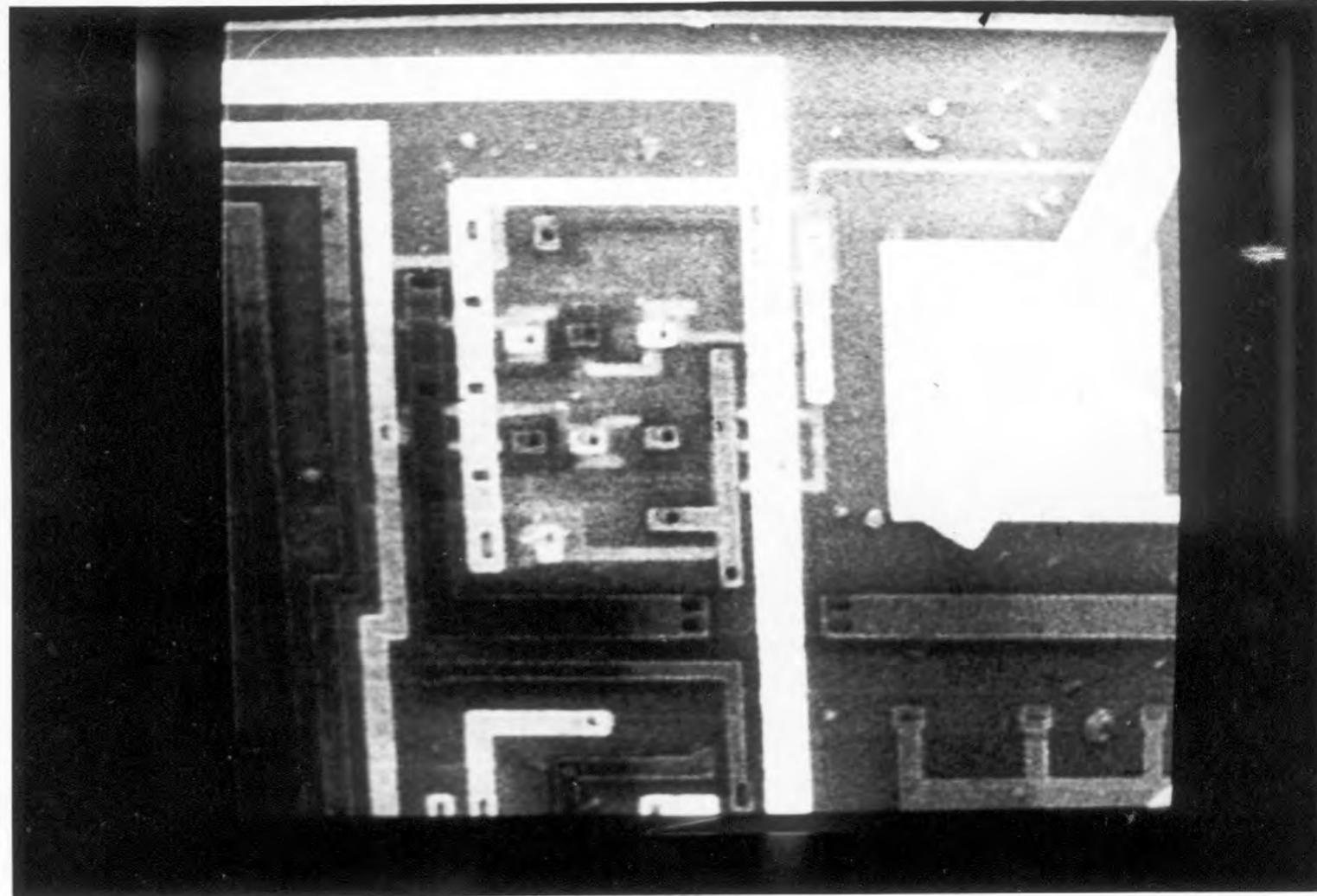


Observation of DC Signals (A= x500)  
Carlos Hurtado 1986

# Visualization of Working Chips using E-Beam Microscope



View of the Clock Pad with two phases with an optical microscope (A= x200)



View of the Clock Pad at phase I with an EBeam microscope (A= x200)

a new proposal...

A tool to emulate an E-Beam  
Microscope but using colors

one color for each layer

Dark color - zero

Light color - one

ex: dark blue - zero

light blue - one

# Why Visualization Tools?

NanoCMOS design involves a **huge** amount of **information!**

Visualization tools associated to EDA tools helps to...

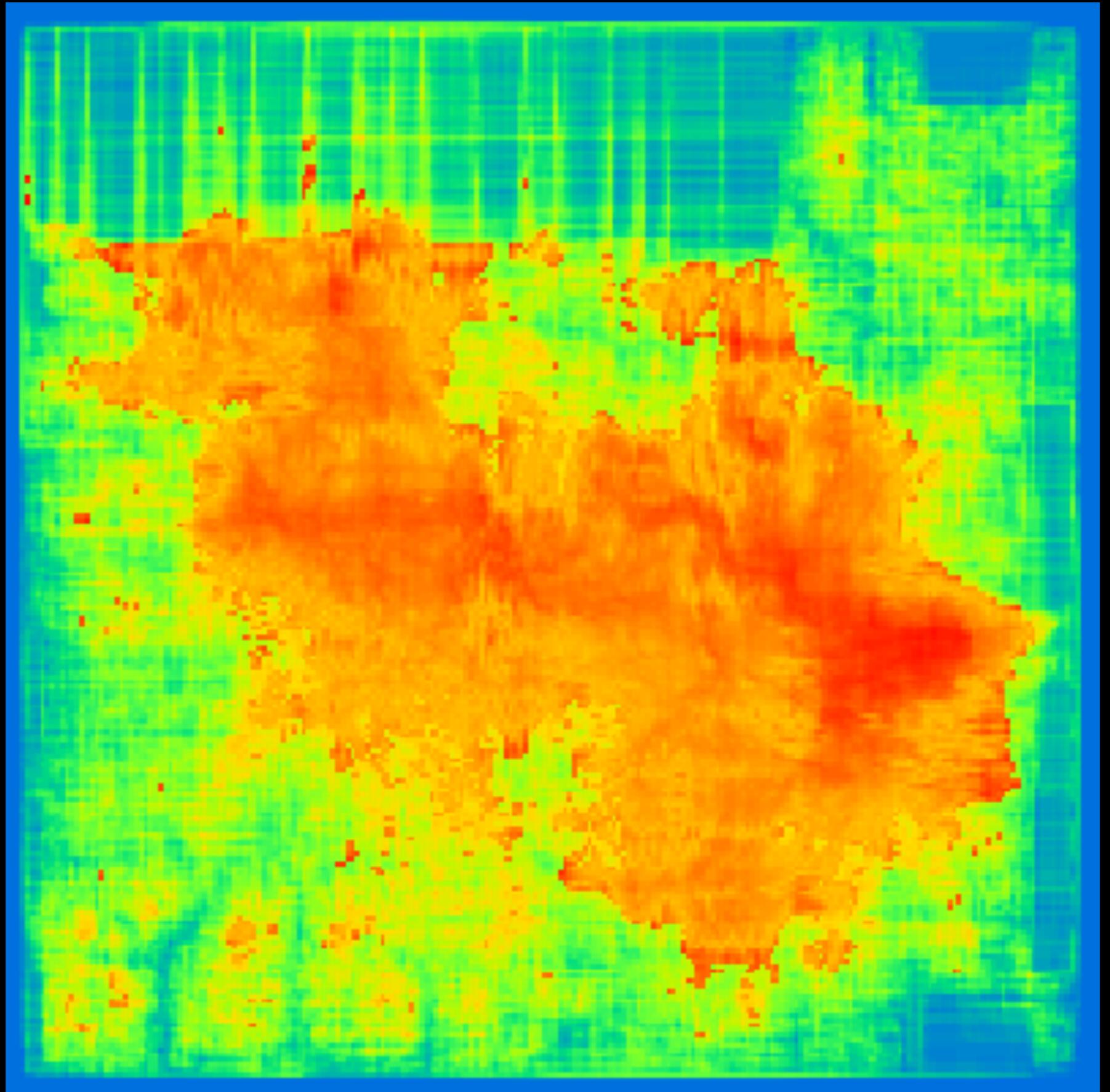
... **understand** an algorithm behaviour

... **evaluate** the quality of a solution

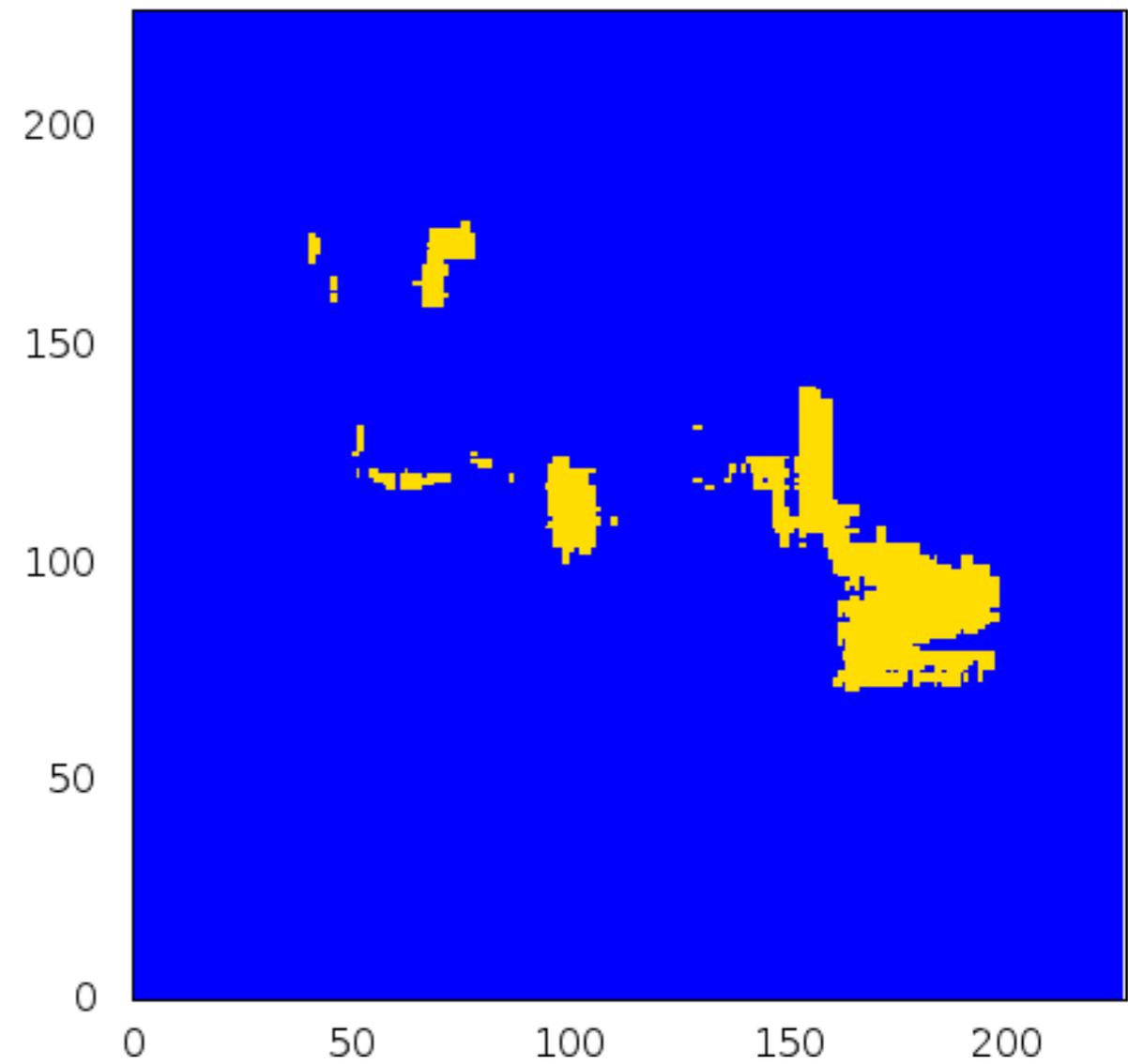
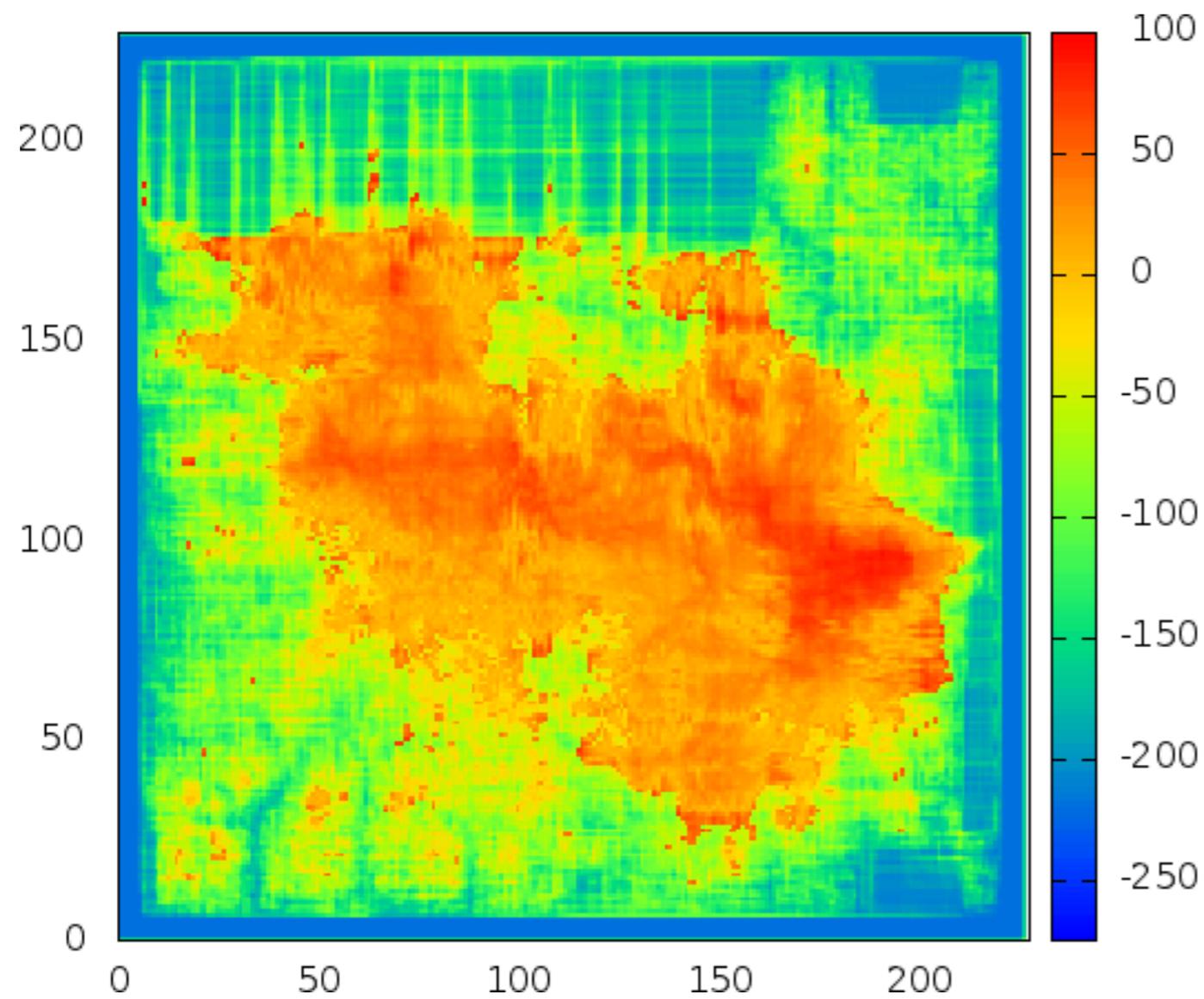
... design **debug**

... design **improvement**

# Hot Spot



# Hot Spots Detection...



# SET Simulation Results

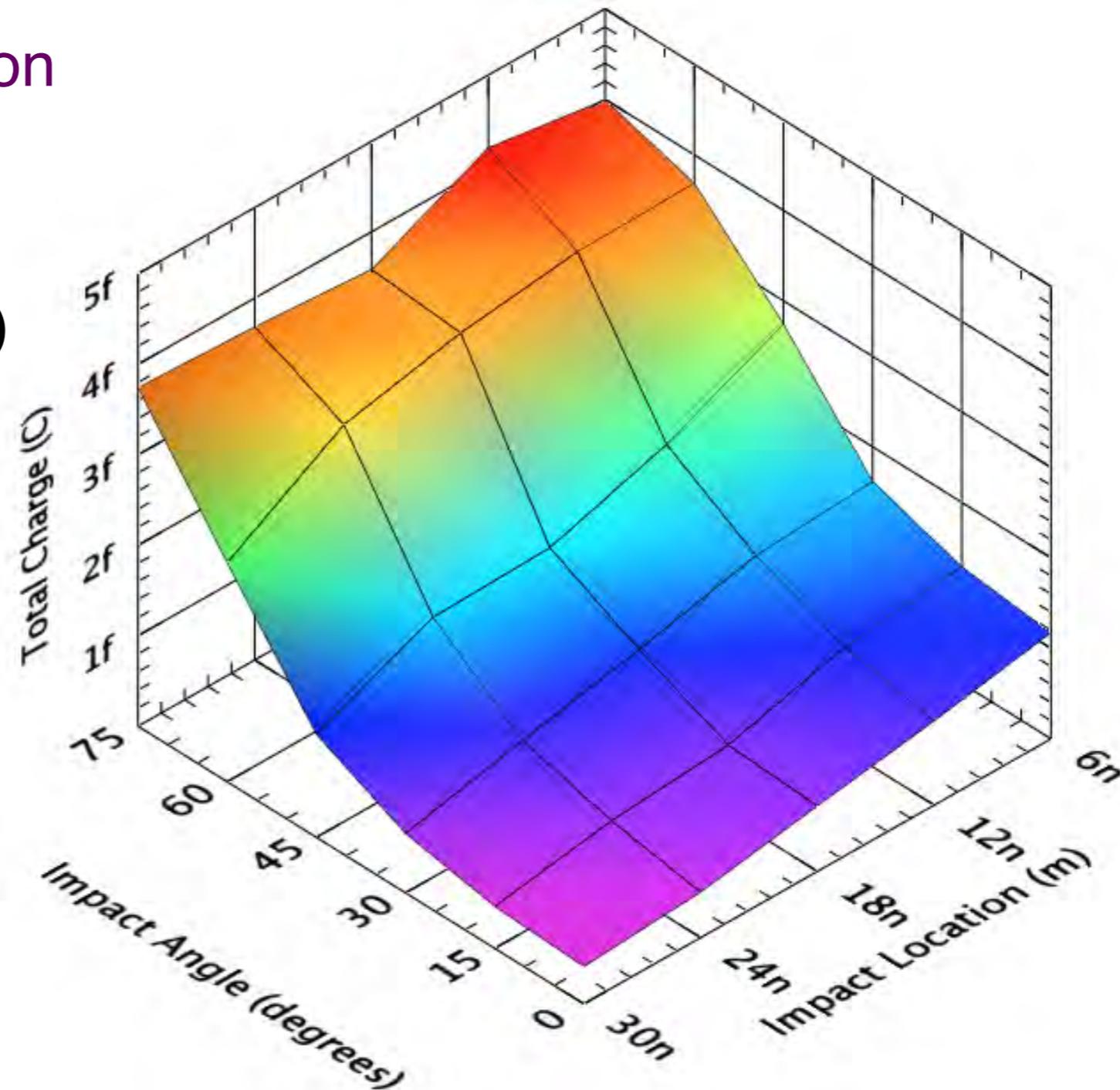
28nm FDSOI Drain Heavy Ion  
impact case:

$CC_{\max} = 4.20\text{fC}$  ( $L_i = 12\text{nm}$ ,  $\theta = 75^\circ$ )

$CC_{\min} = 0.41\text{fC}$  ( $L_i = 30\text{nm}$ ,  $\theta = 0^\circ$ )

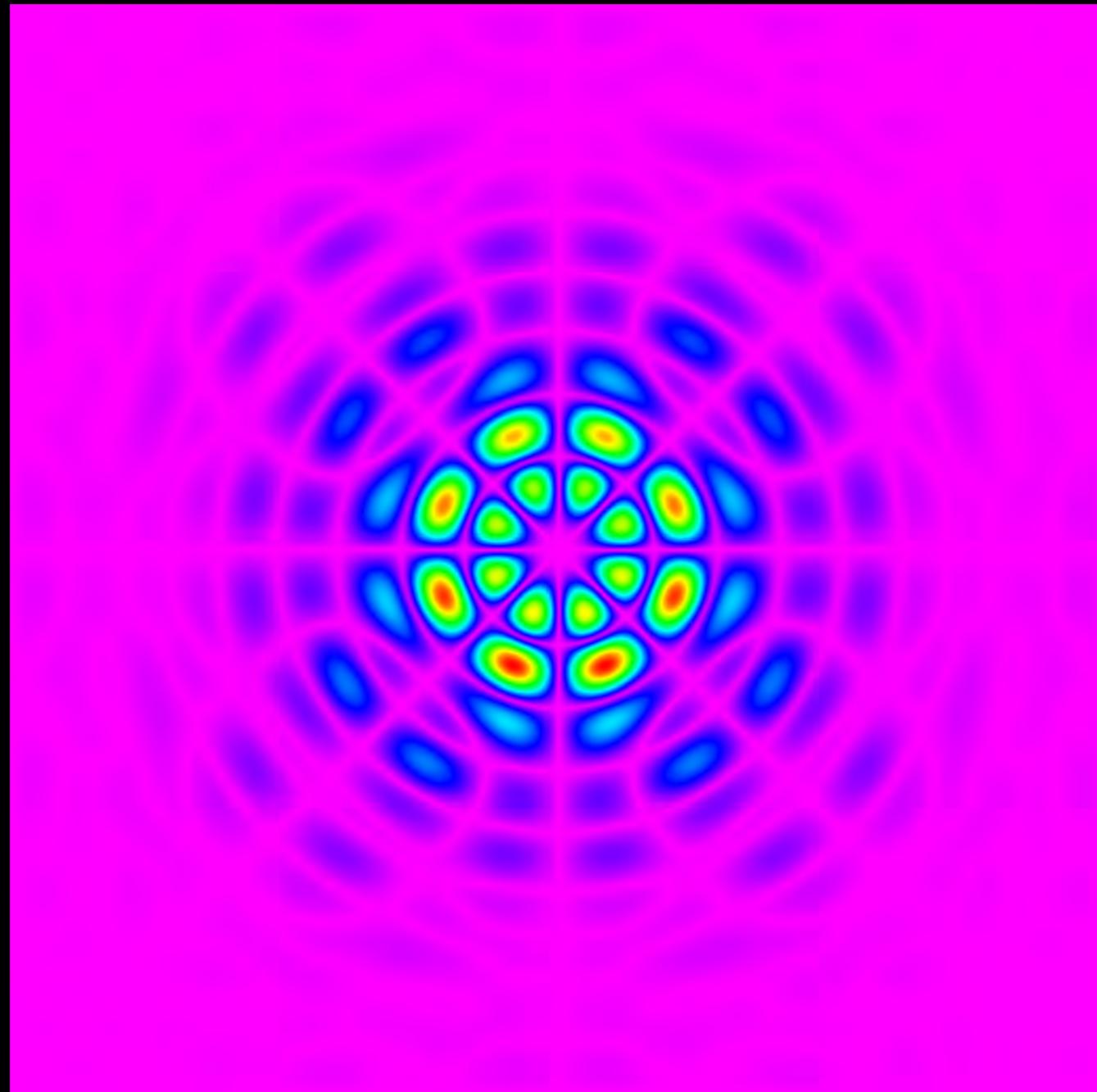
When  $L_i$   $\uparrow$   $\rightarrow$  CC  $\downarrow$  .

When  $\theta$   $\uparrow$   $\rightarrow$  CC  $\uparrow$  .



by Walter Bartra

A Tool to Simulate  
**Optical Lithography**  
in NanoCMOs

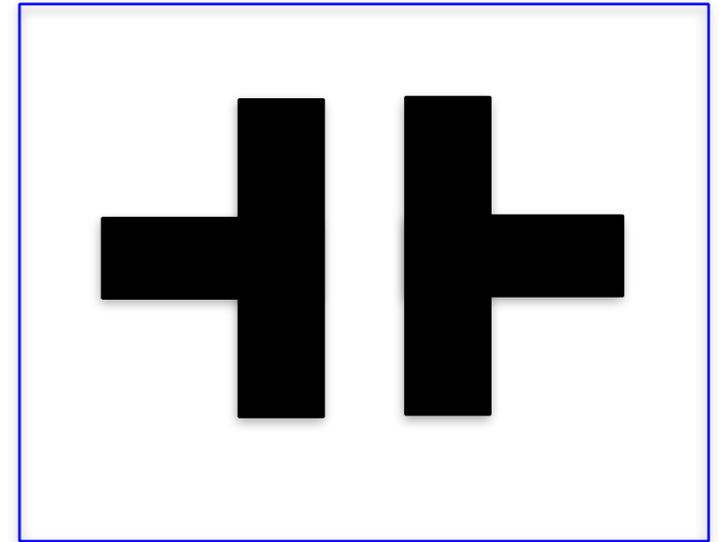


Tania Mara Ferla, Guilherme Flach, Ricardo Reis

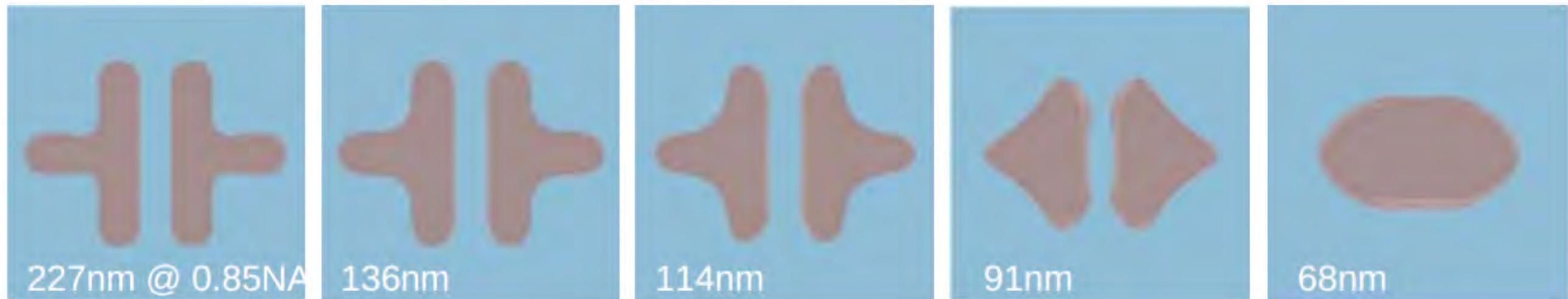
OBS: This and other pictures will be presented at the DAC ART SHOW, Austin, Texas, June 6-9, 2016

# A Problem in NanoCMOs

Why optical lithography is an issue?  
Lost of resolution in  
nanometric technologies.



Technology Scaling



NTUEE/Y.-W. Chang

... and the technology node is at 14nm

Lithography Systems Evolution did not followed! the technology scaling

# Diffraction Problem: Some solutions...

## Improvements in optical lithography system

Example: reduction of the wavelength

## RET (resolution enhancement techniques):

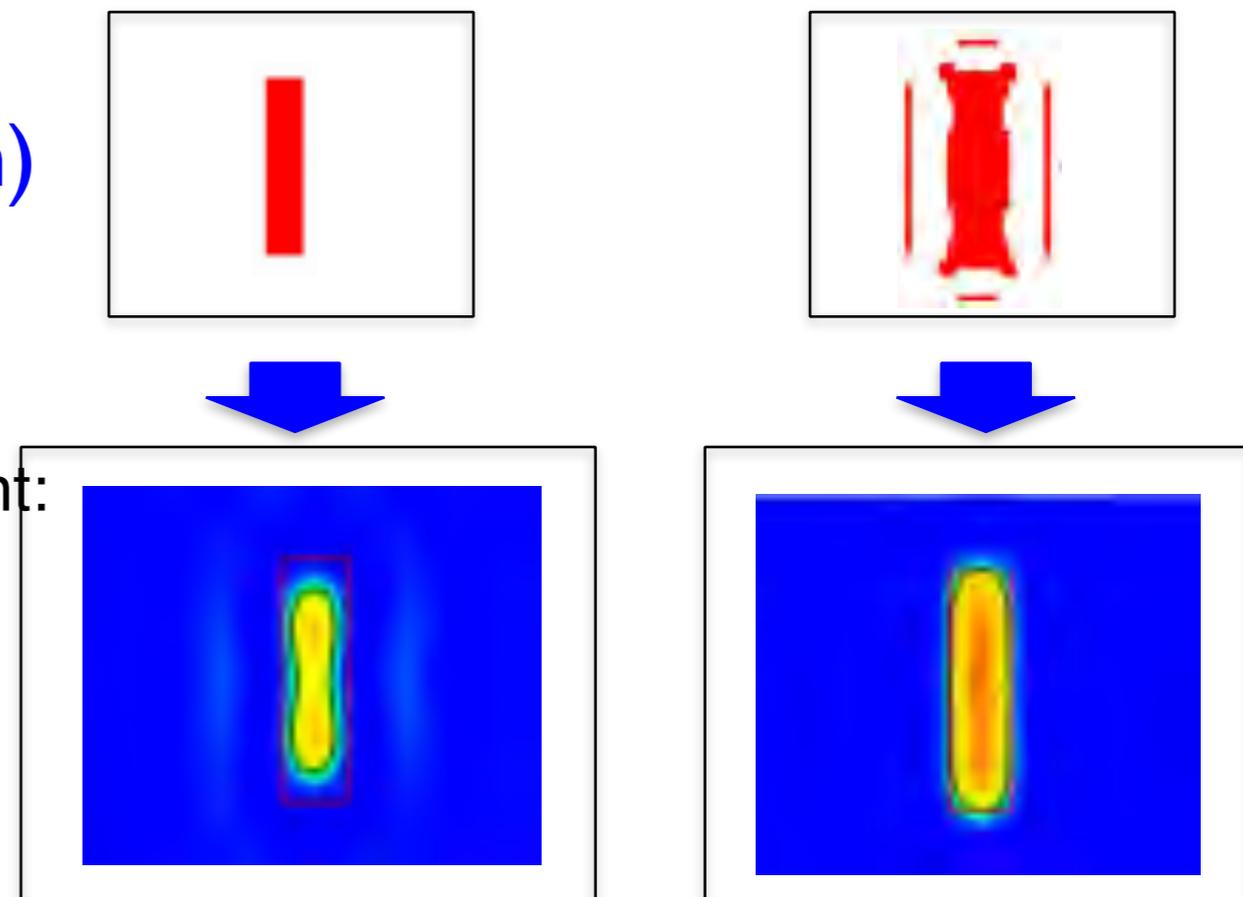
- DPL / MPL (multiple and double patterning lithography)
- RDR (Restricted Design Rules)
- OPC (Optical Proximity Correction)
- Regular Layout

Other Lithography Technologies under development:

Extreme Ultra-Violet Lithography (EUV)

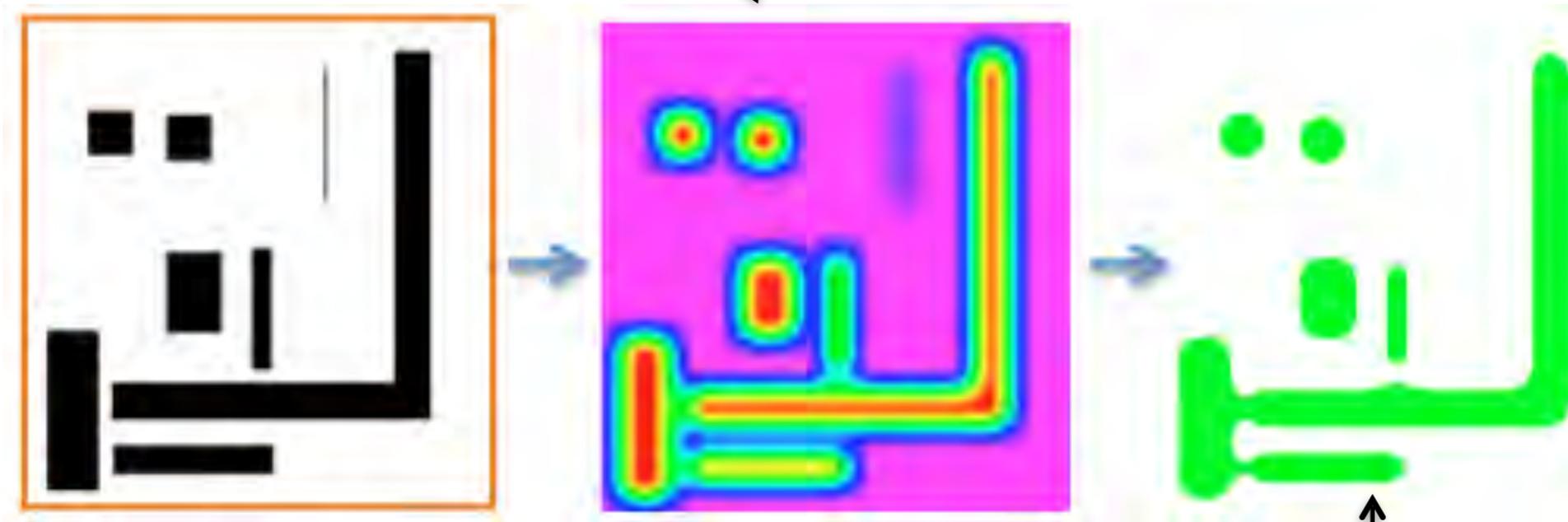
E-beam direct-write (EBDW)

Directed self-assembly (DSA)



# Example of Simulation with the Tool

Intensity map generated by the convolution



Mask

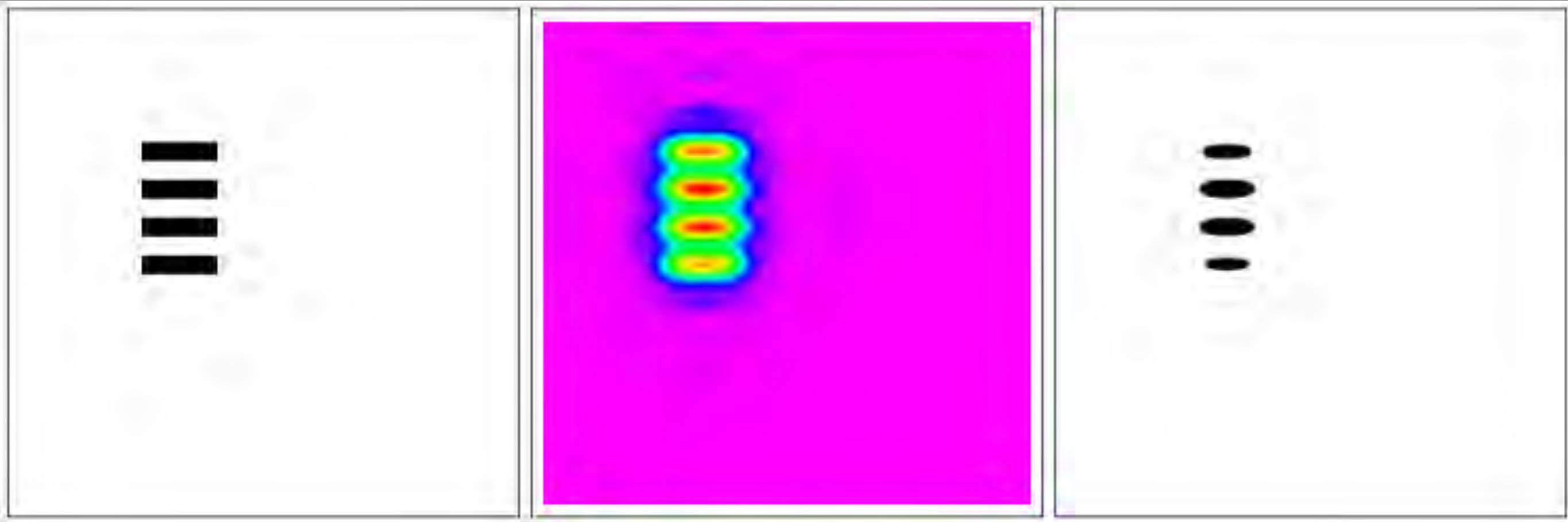
How would print the mask



Edge Placement Error (EPE)

# Lithux

## EDA tool for Lithography Simulation



Mask

Intensity Map

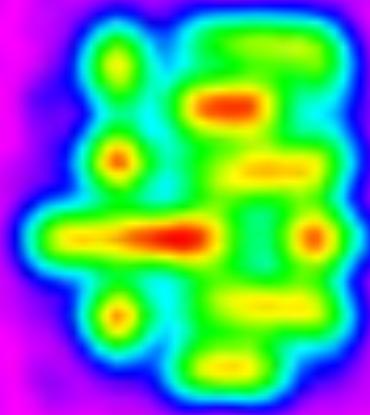
Printing Pattern

# Lithux

## EDA tool for Lithography Simulation



Mask



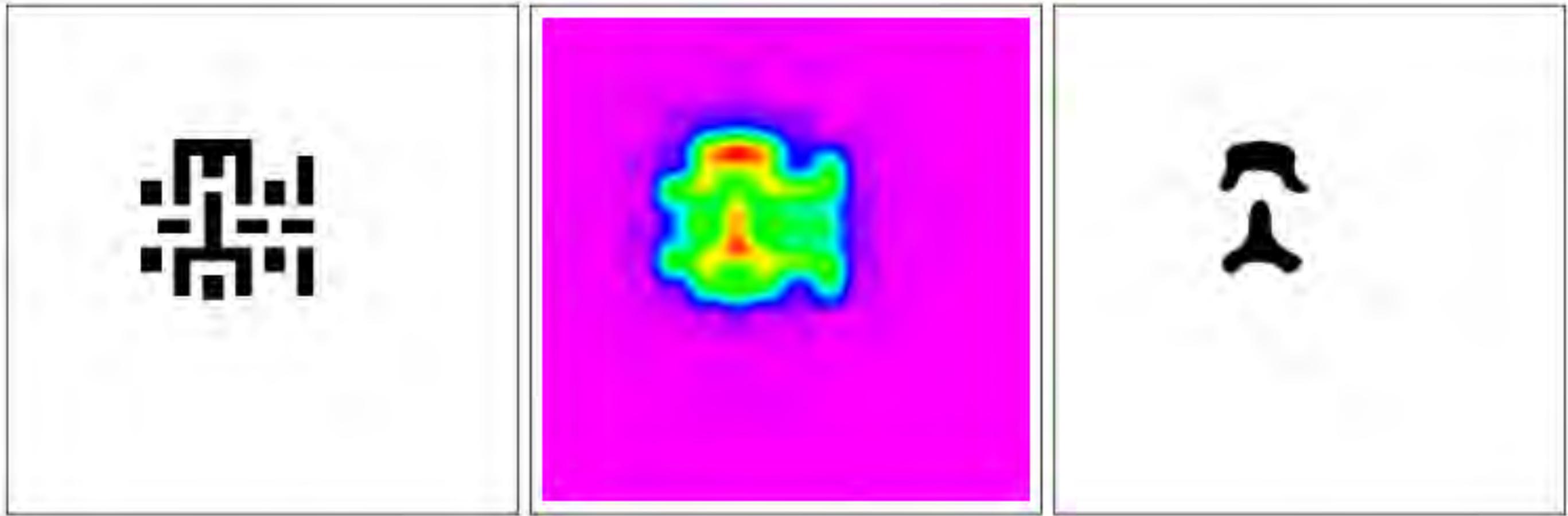
Intensity Map



Printing Pattern

# Lithux

## EDA tool for Lithography Simulation



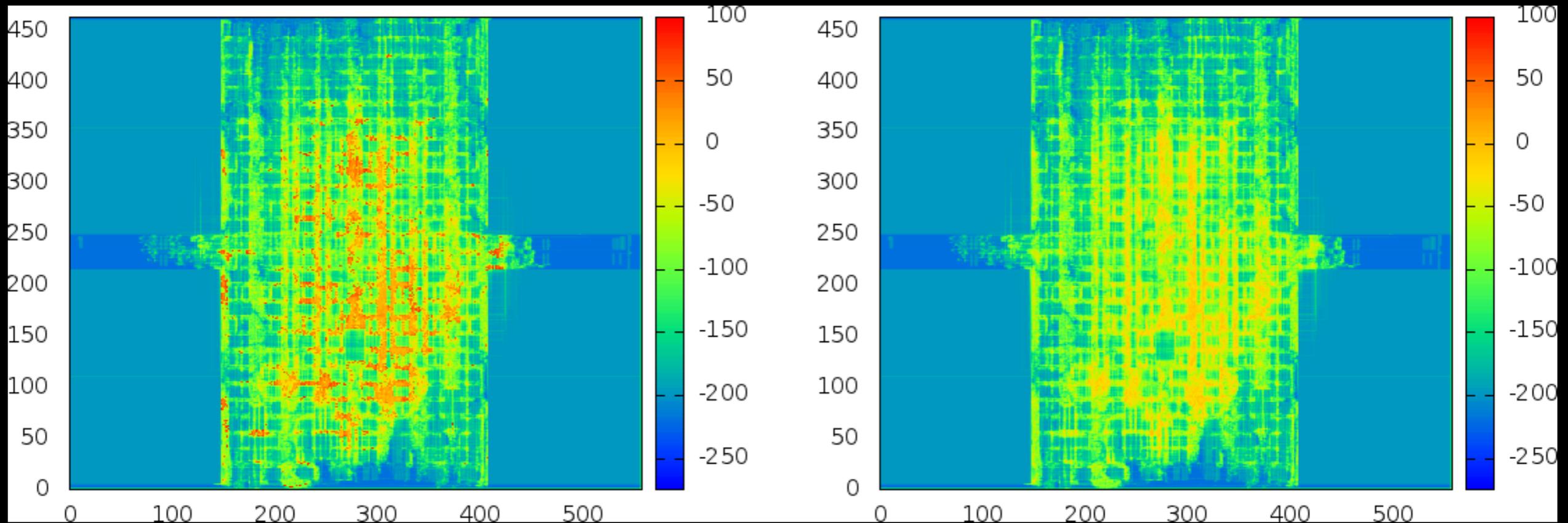
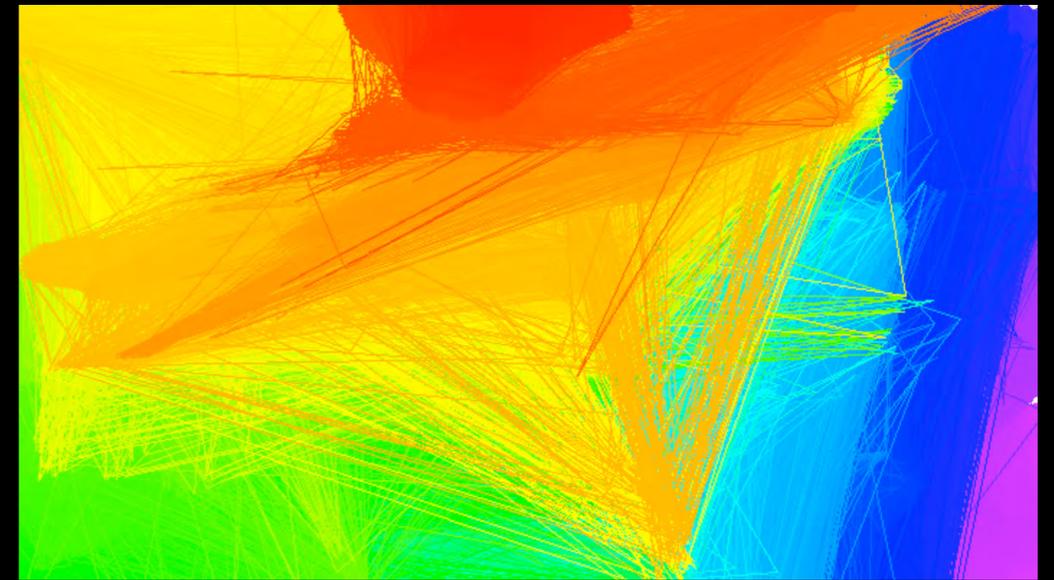
Mask

Intensity Map

Printing Pattern

# Routing

Global Routing  
Detailed Routing



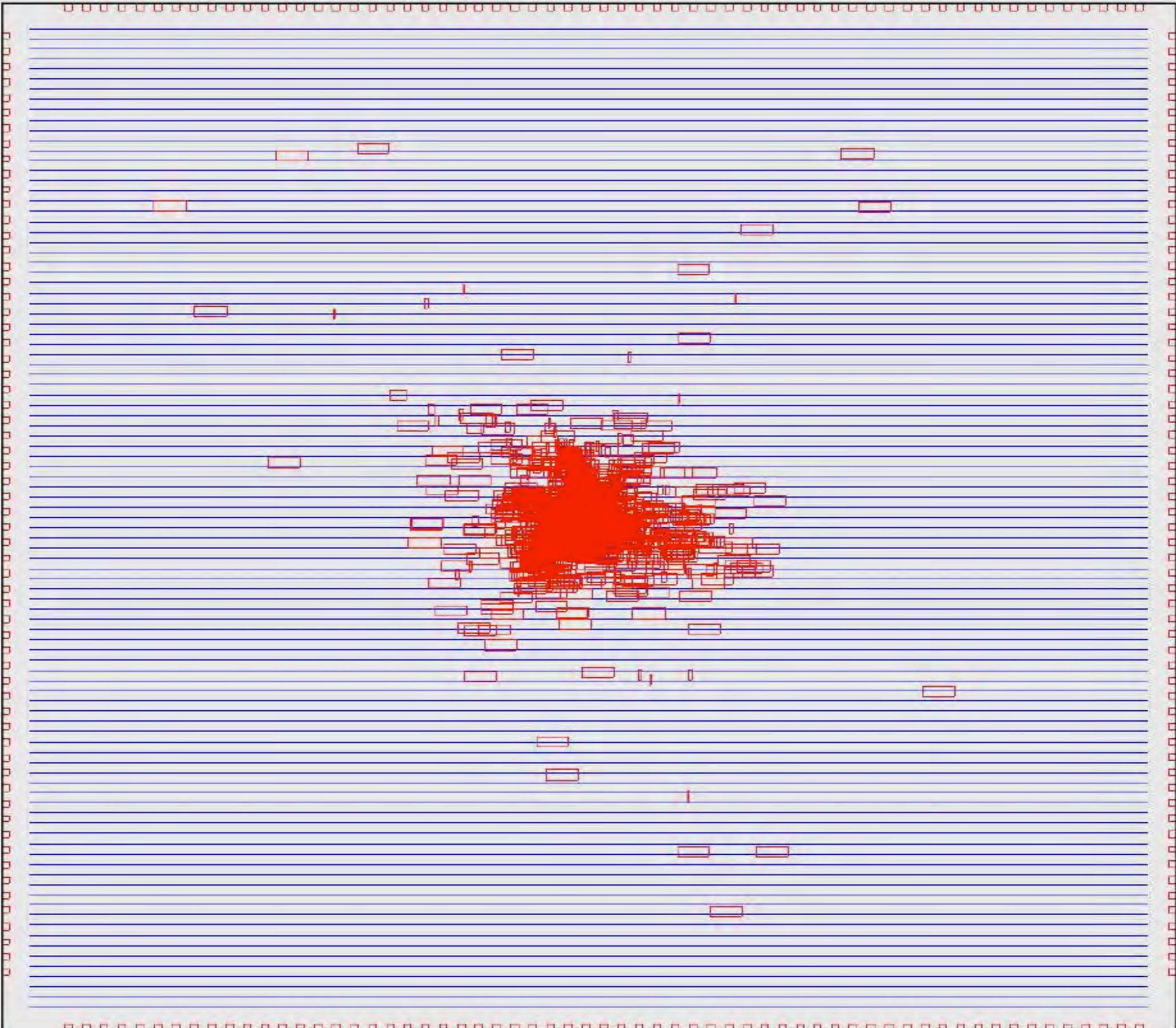
Congestion Map

# Visualisation Tools

helping

Placement tools

improvement



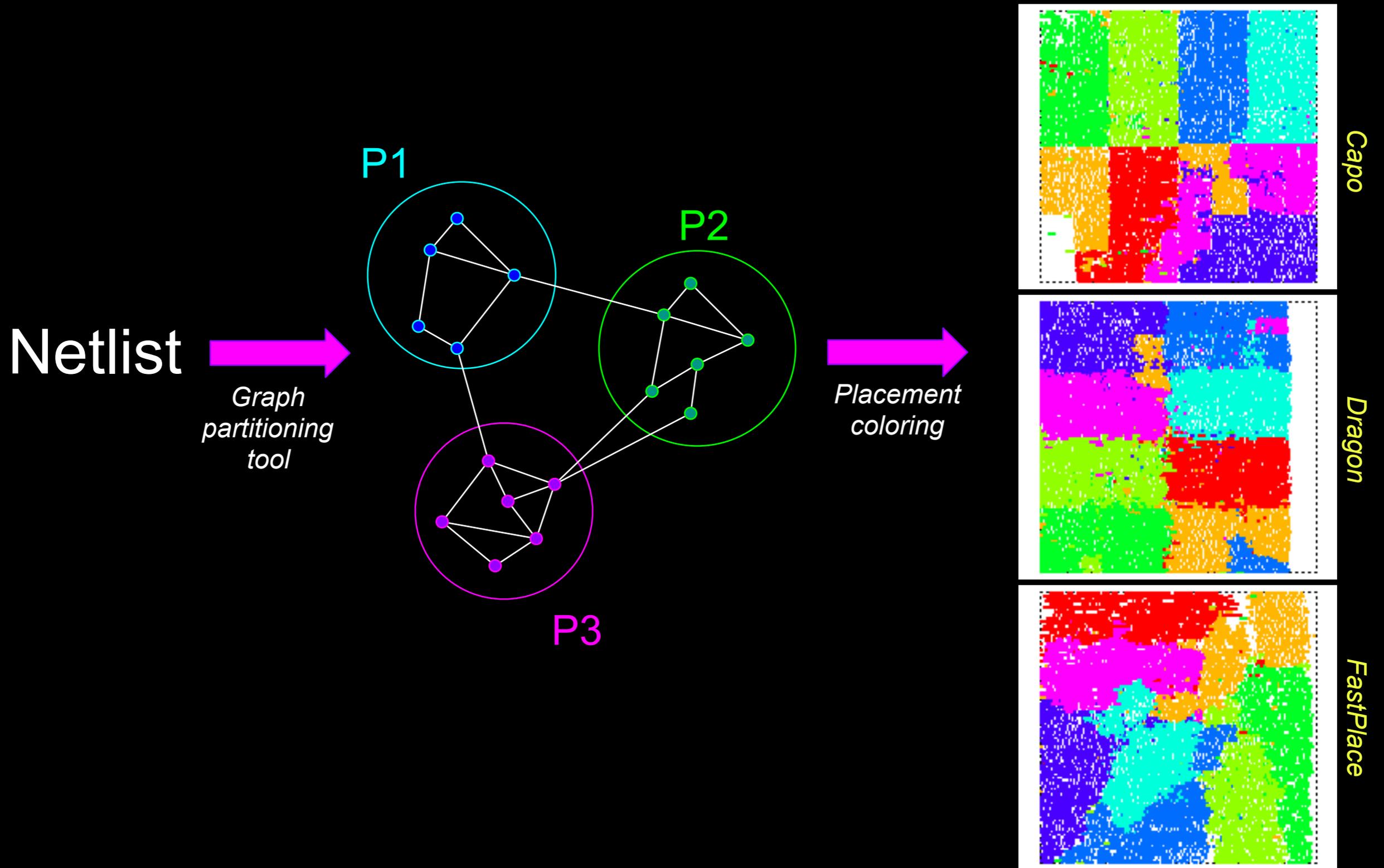
**Understanding**

an

Algorithm

Behaviour

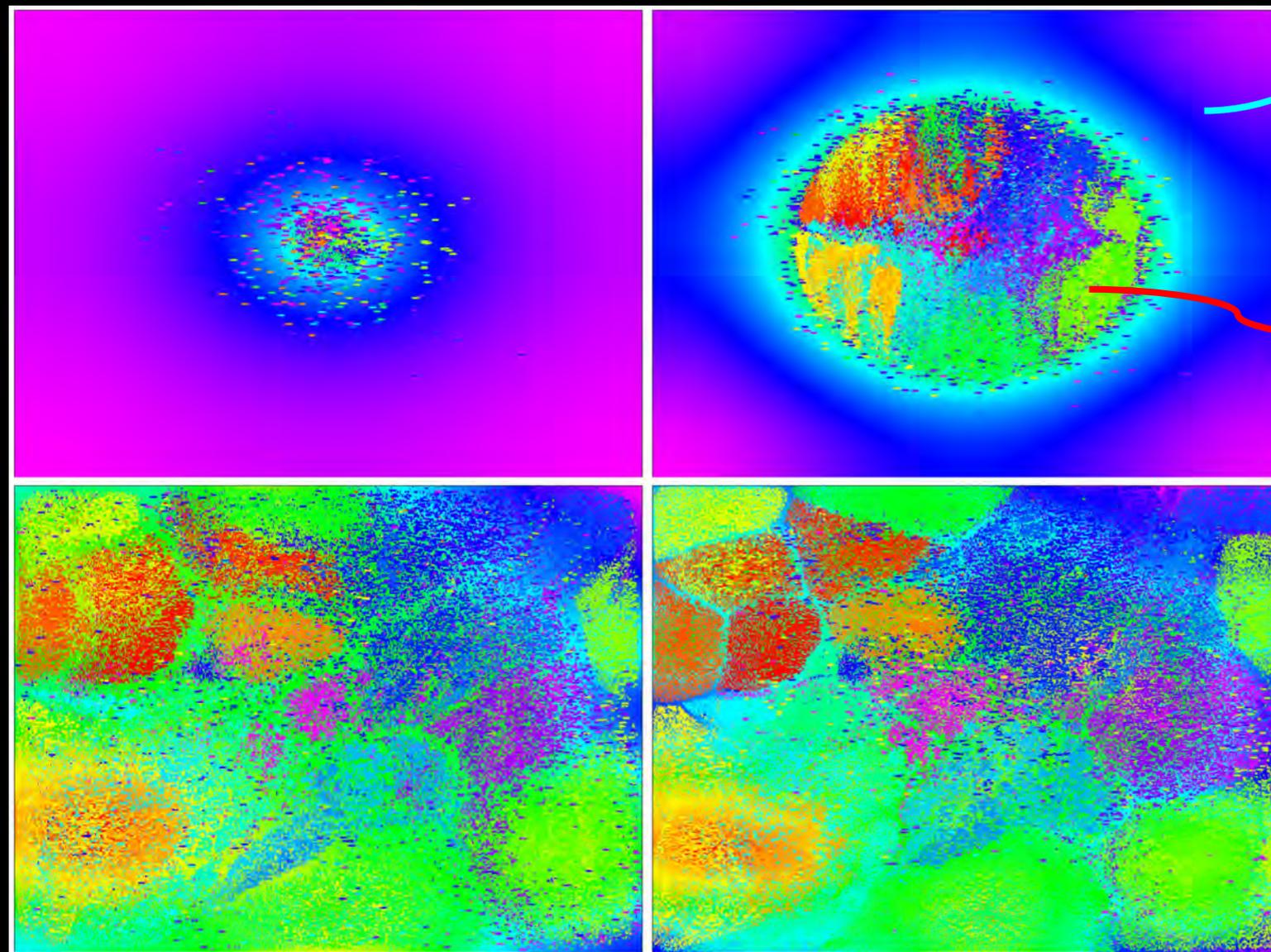
# Placement Colouring<sup>1</sup>



<sup>1</sup> Experiments performed by Guilherme Flach

**Evaluating**  
the  
**Quality**  
of a Solution

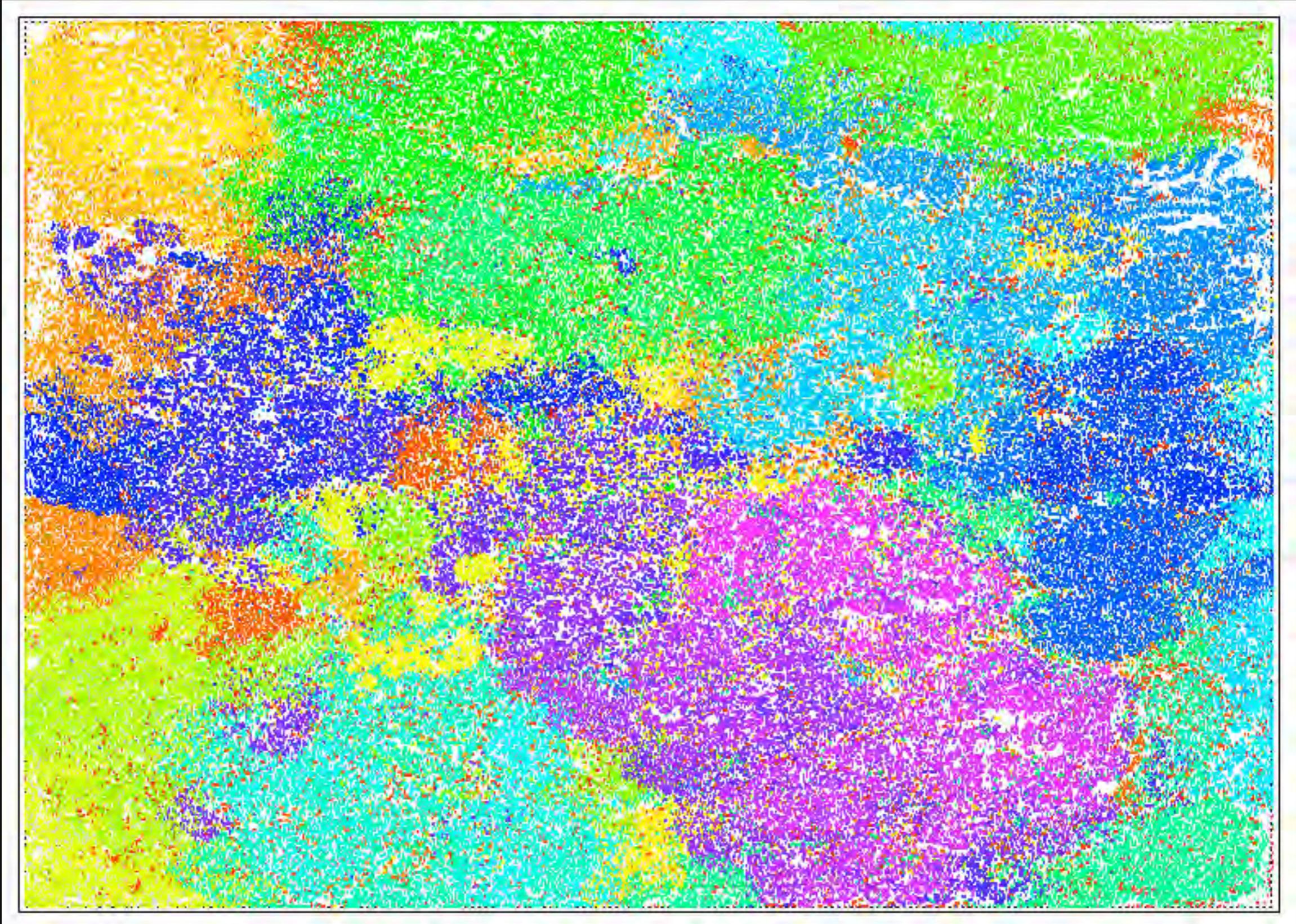
# A global placement algorithm based on Poisson Equation



The **background** is a **heatmap** indicating **congestion**

**Cells** are colored like in the **previous example**

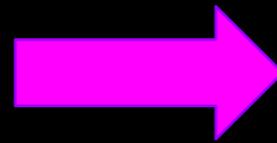
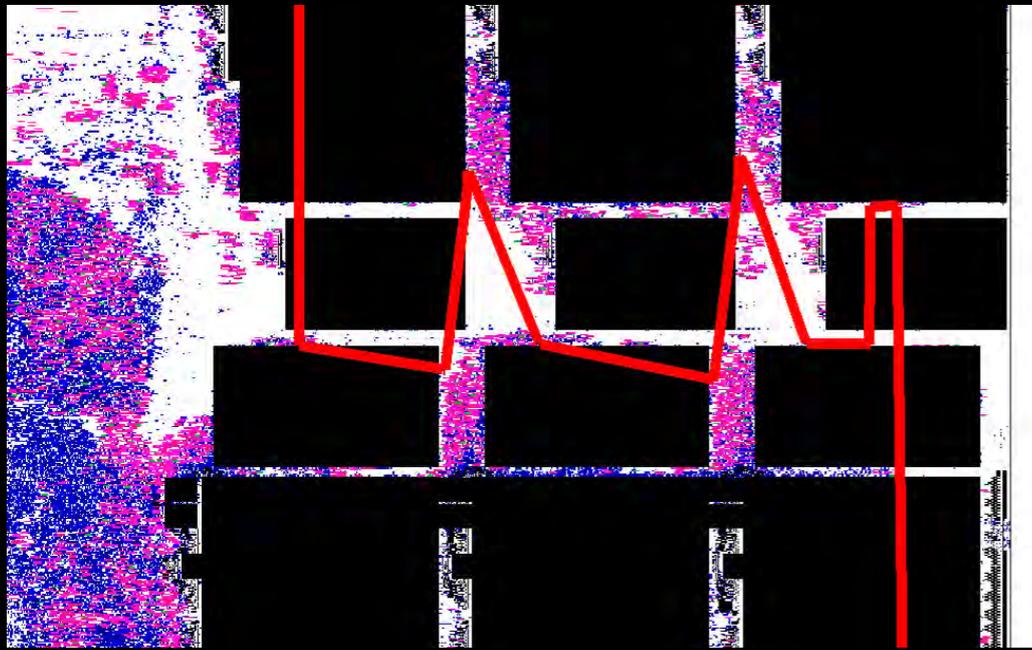
Placement of the IBM18 circuit using UFRGS tools  
> 200 thousand logic cells



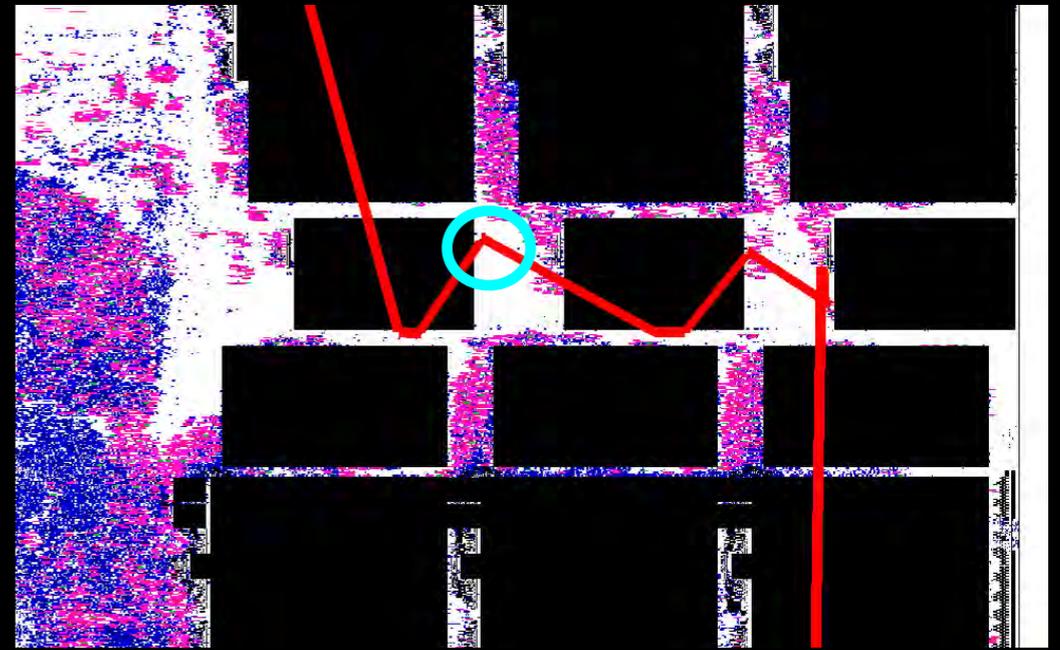
# **Design Debug and Improvement**

# Critical path smoothing for timing-driven placement

Initial solution



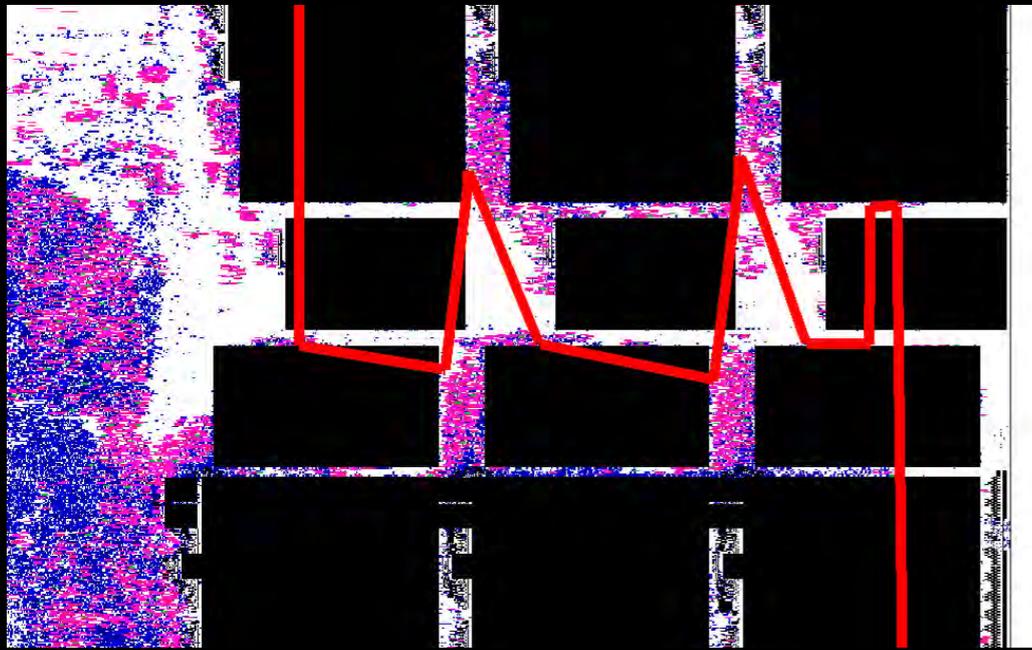
Global optimization



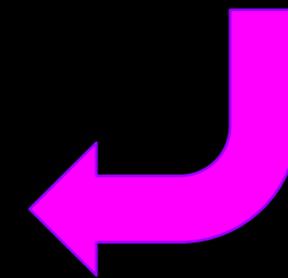
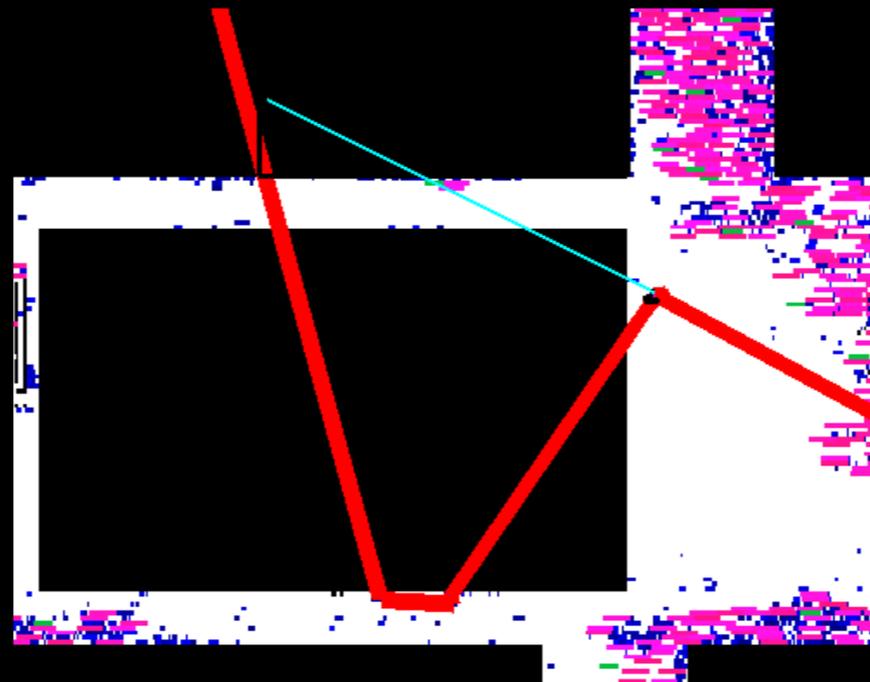
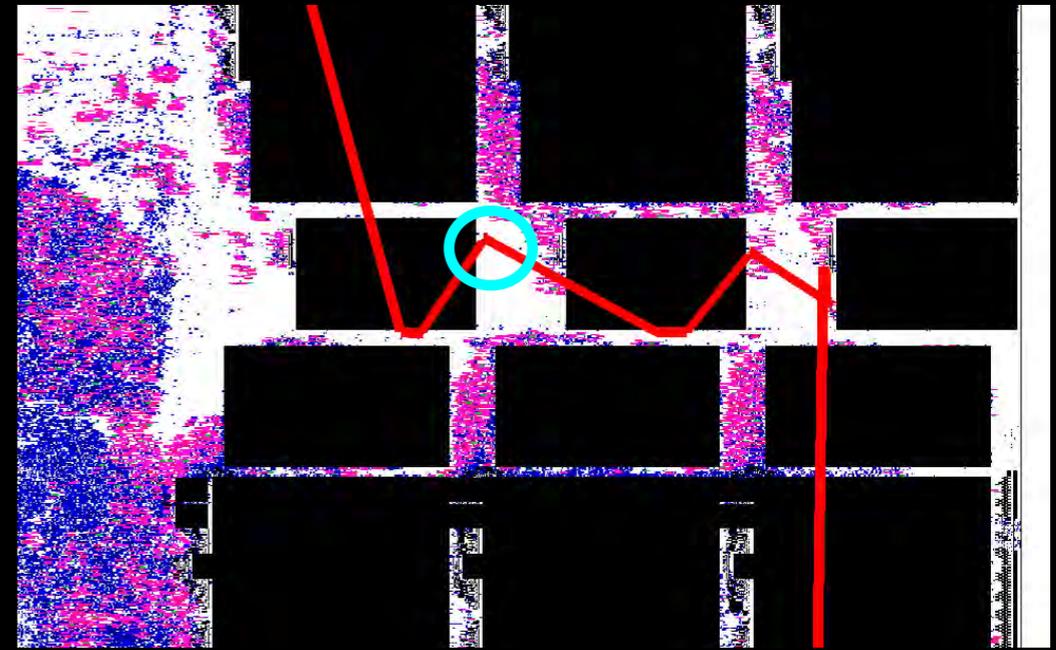
Why not further aligned?

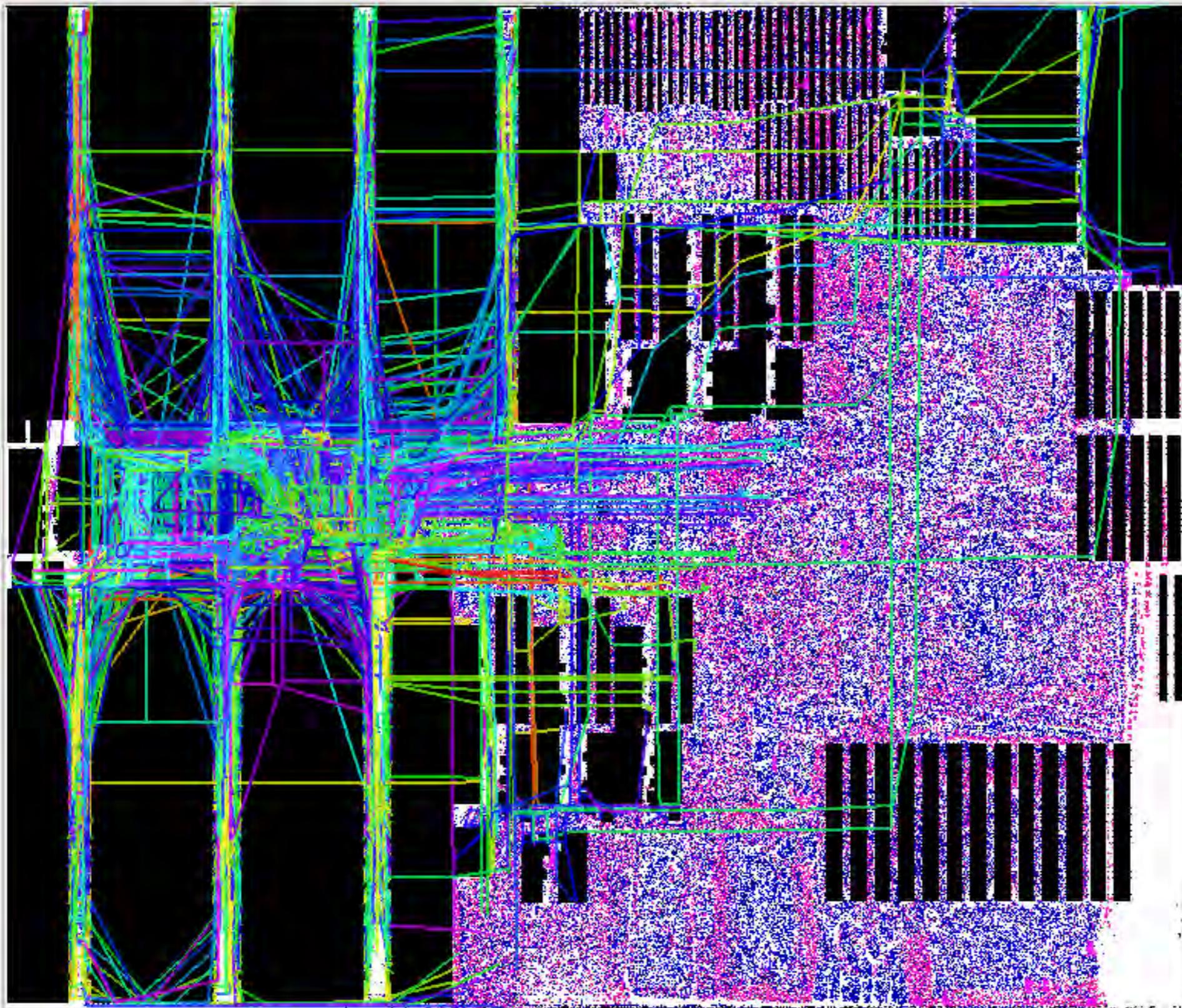
# Critical path smoothing for timing-driven placement

Initial solution



Global optimization



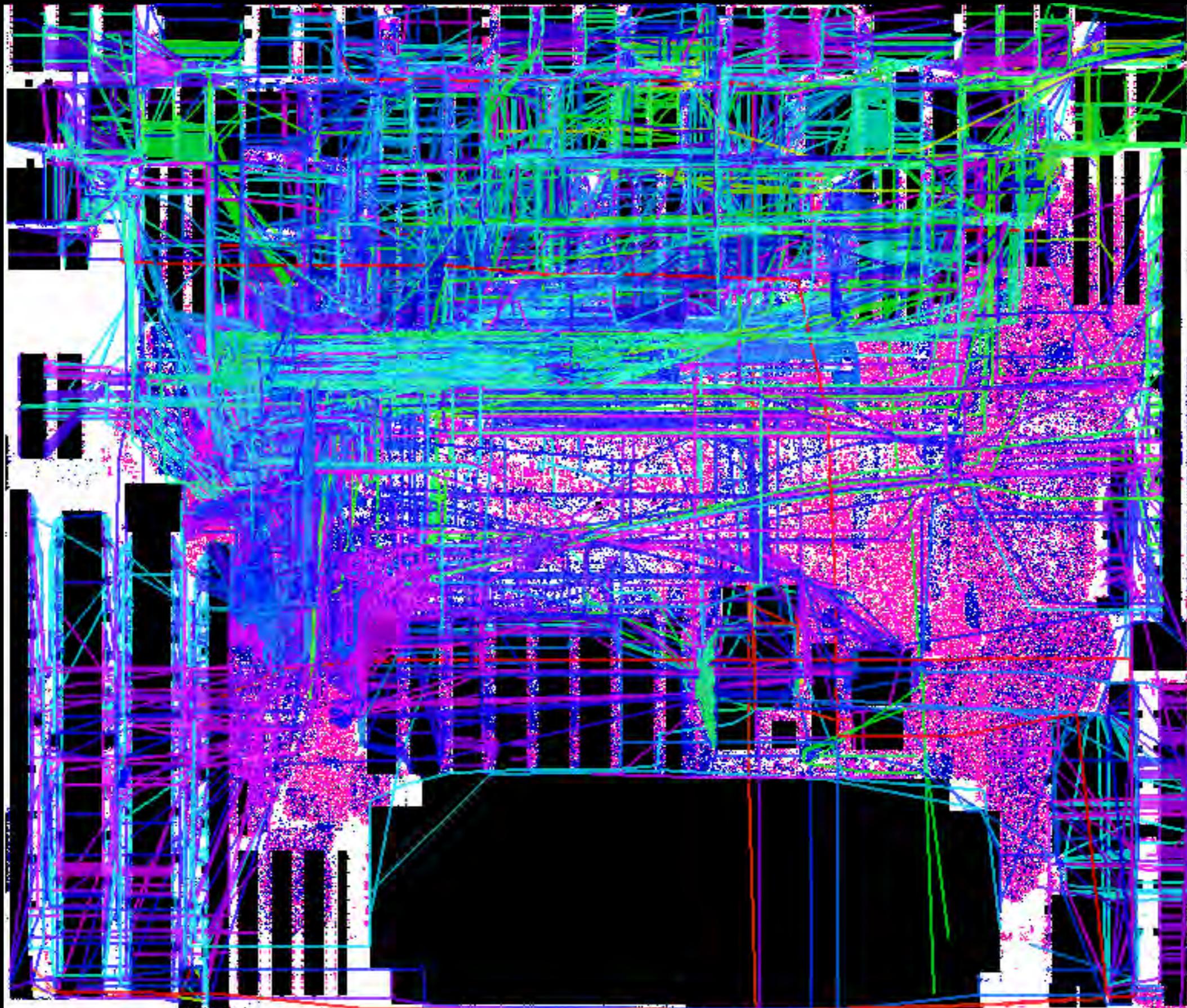


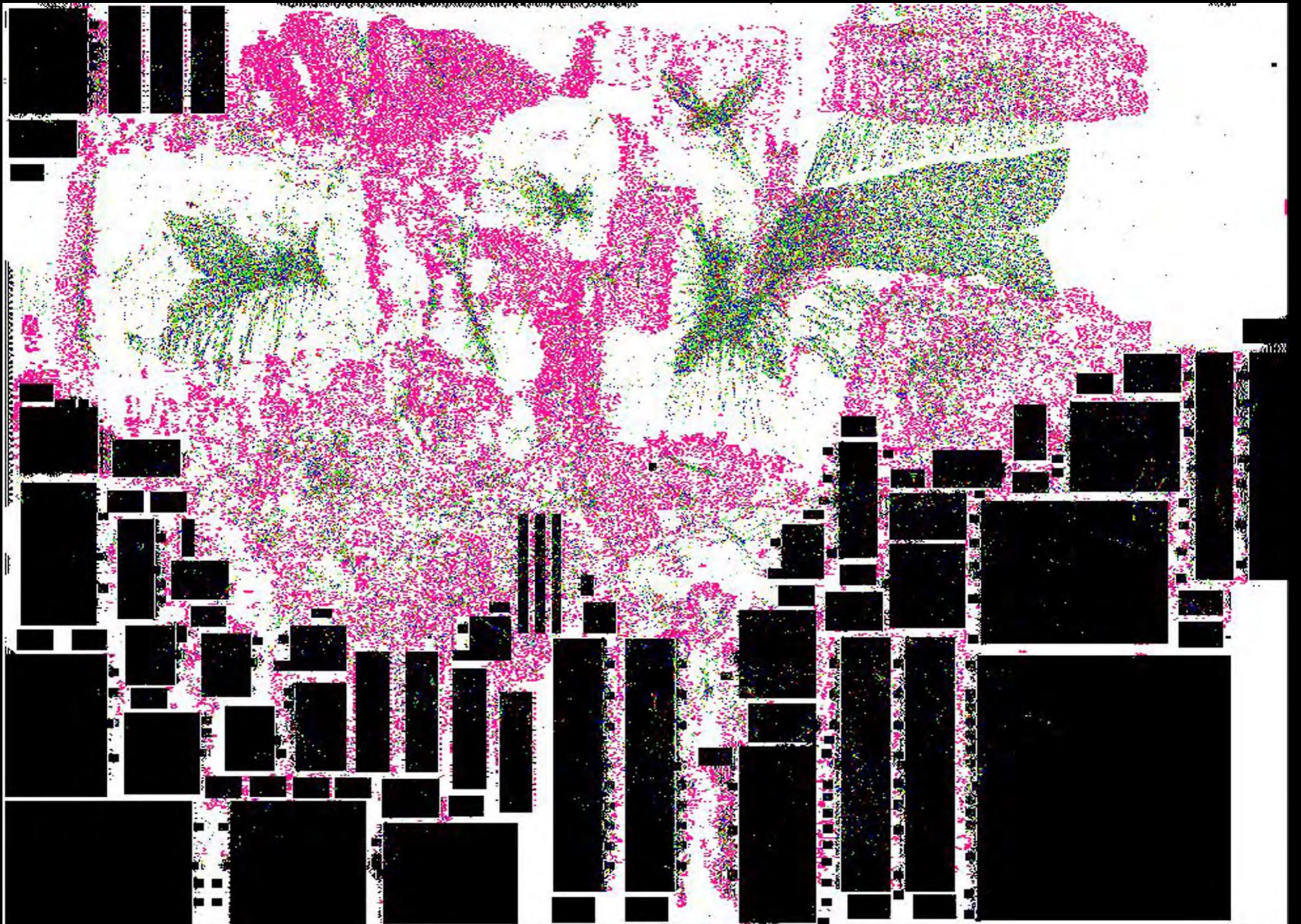
Design Canvas Opto Report

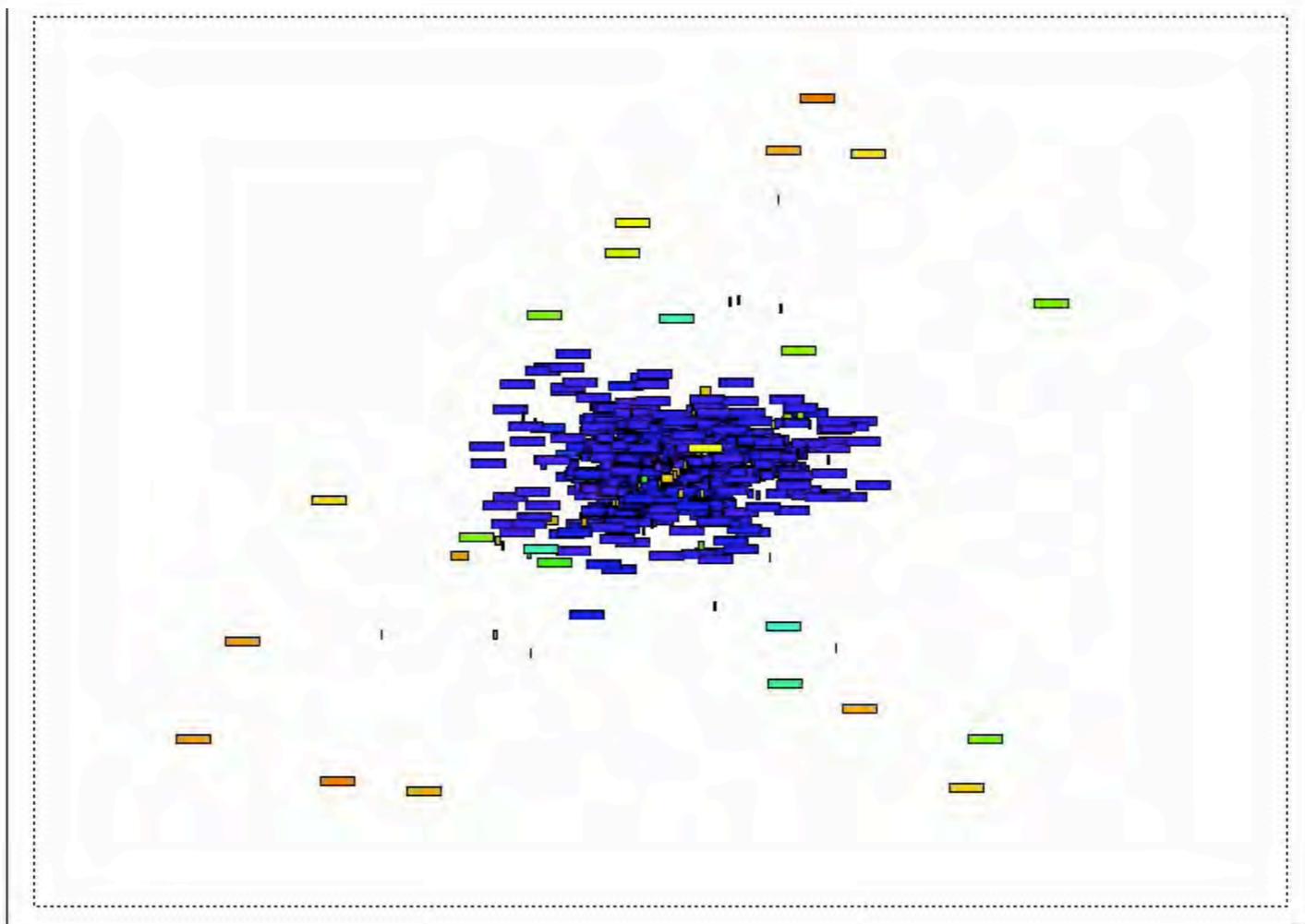
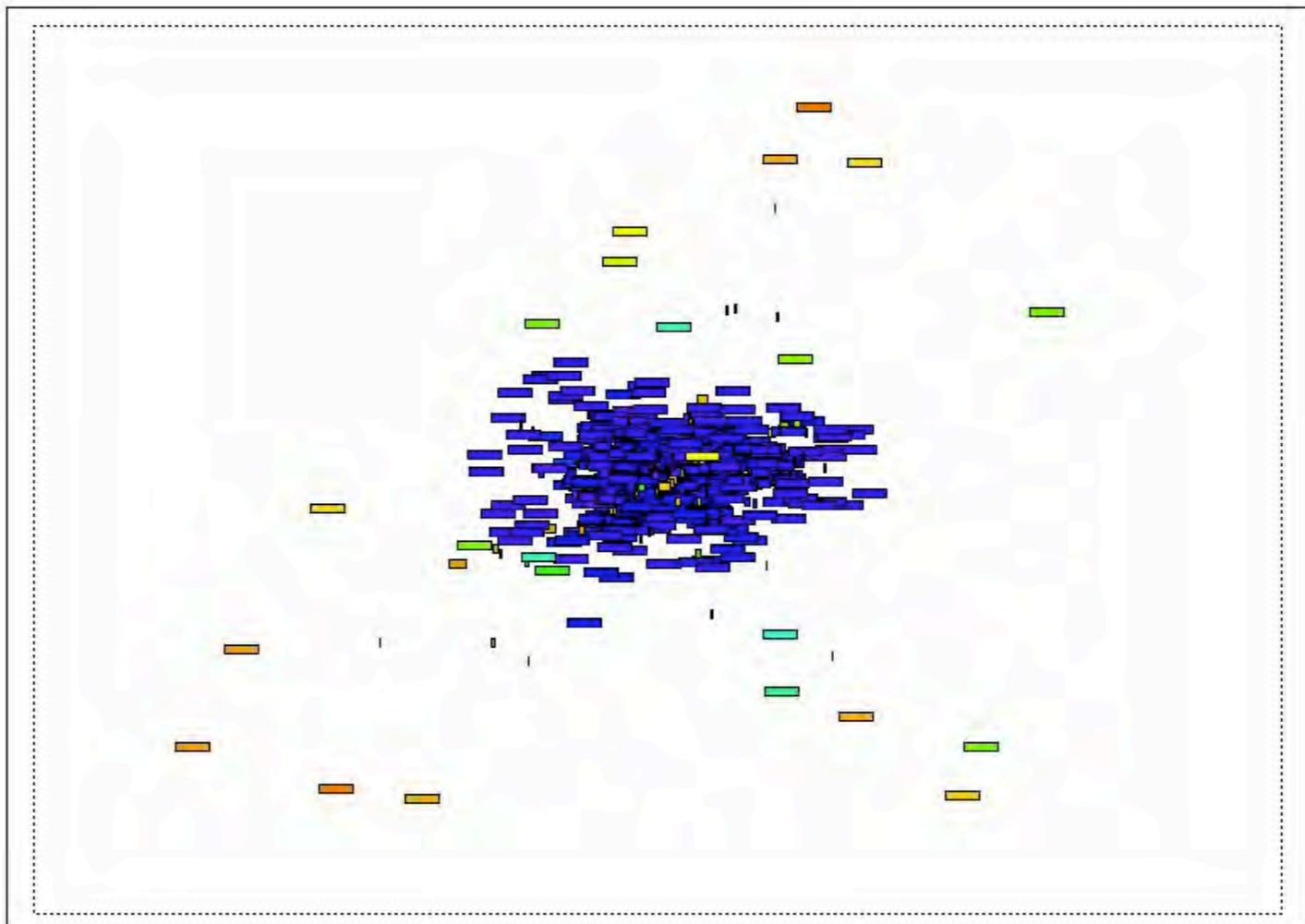
Q Search

Cell

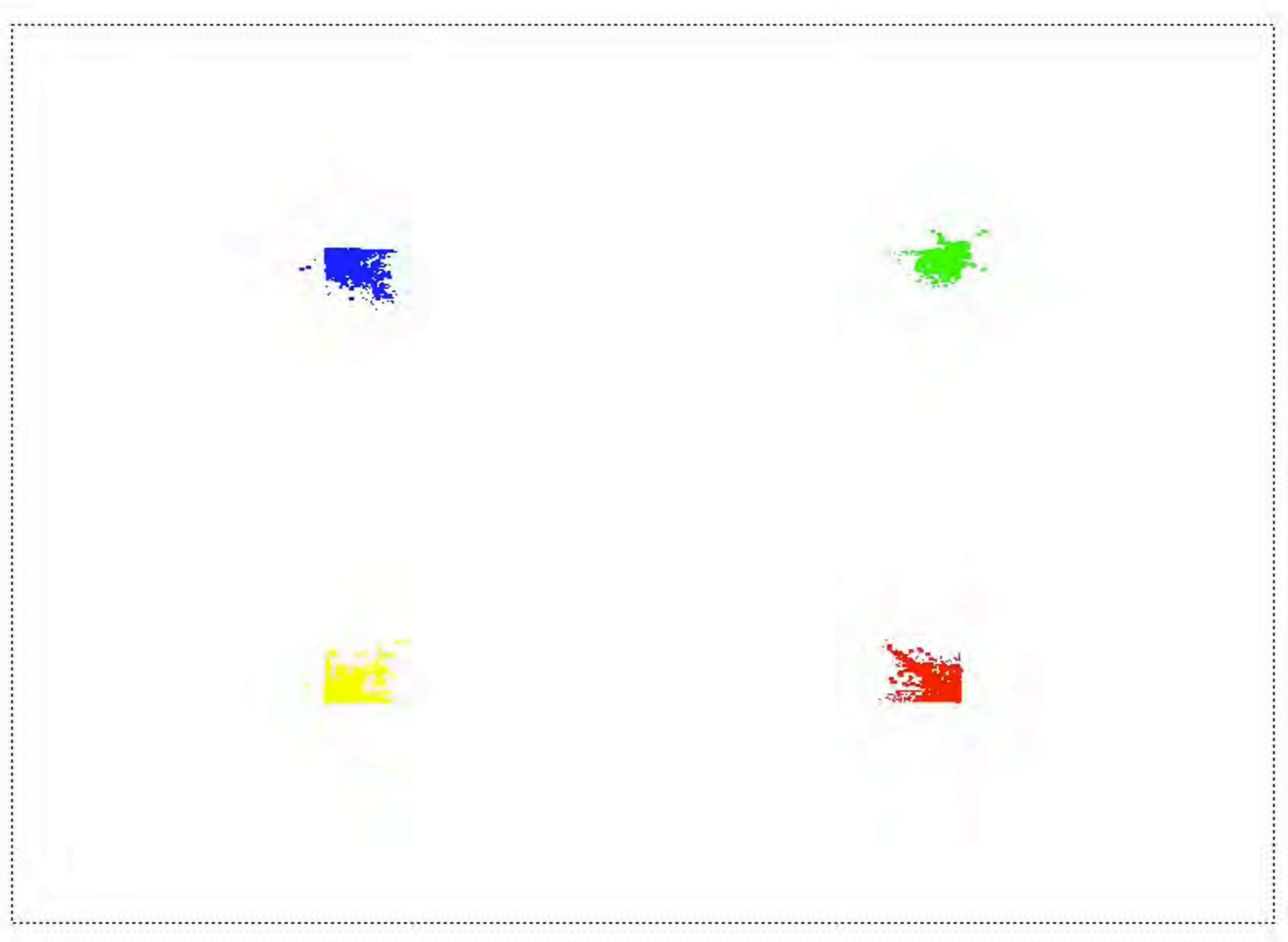
- Name
- LibCell
- Placement
  - X
  - Y
  - Fixed (Current)
  - Fixed (Original)
  - Legalized
- Dimension
  - Width
  - Height
- Timing (Early)
  - Criticality (E)
  - Centrality (E)
- Timing (Late)
  - Criticality (L)
  - Centrality (L)
  - Delay (Max)
  - Wire Delay (Max)
  - Rdrive (Max)
  - Load (Max)





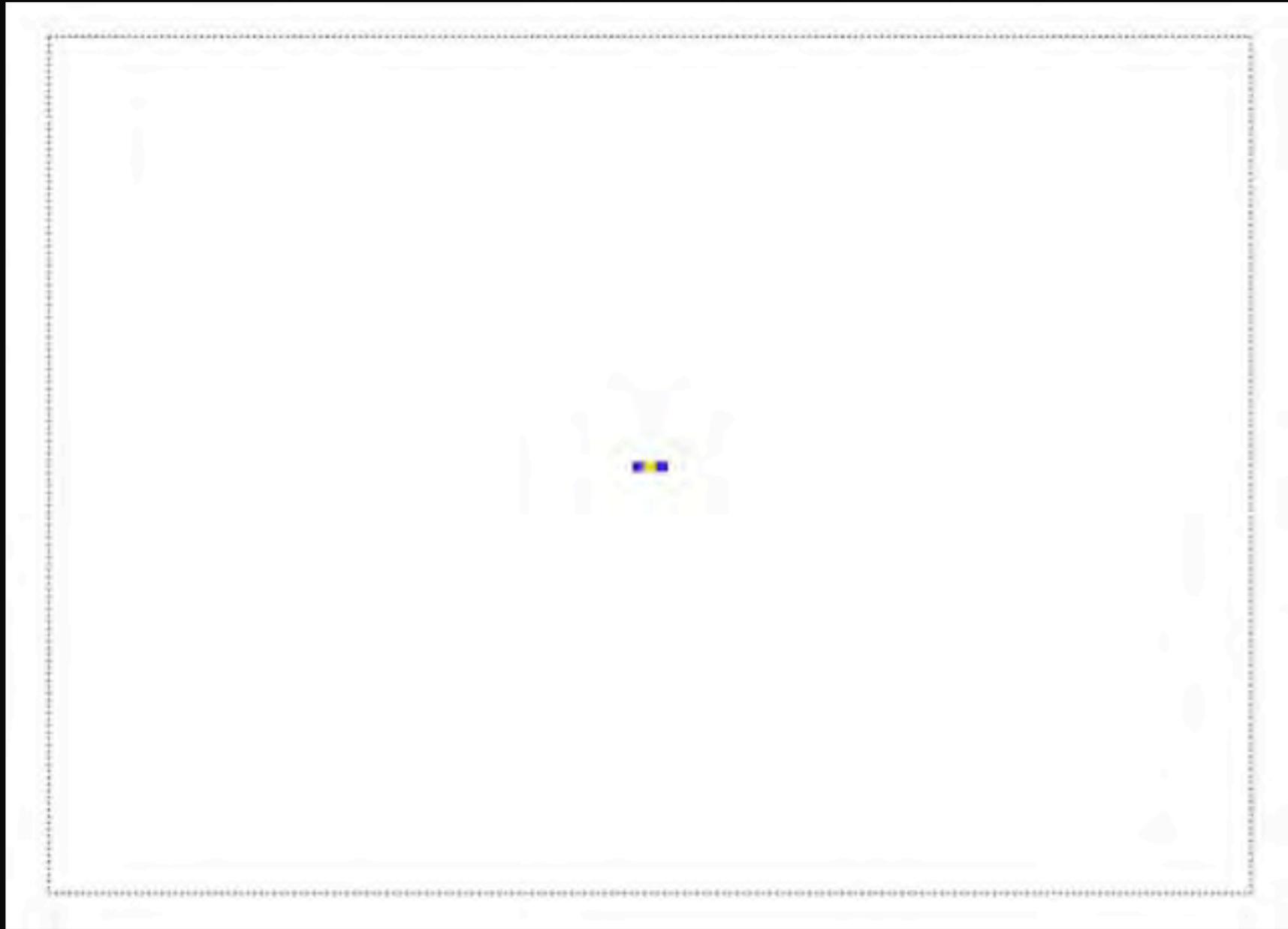


# Placement using PlaceDL



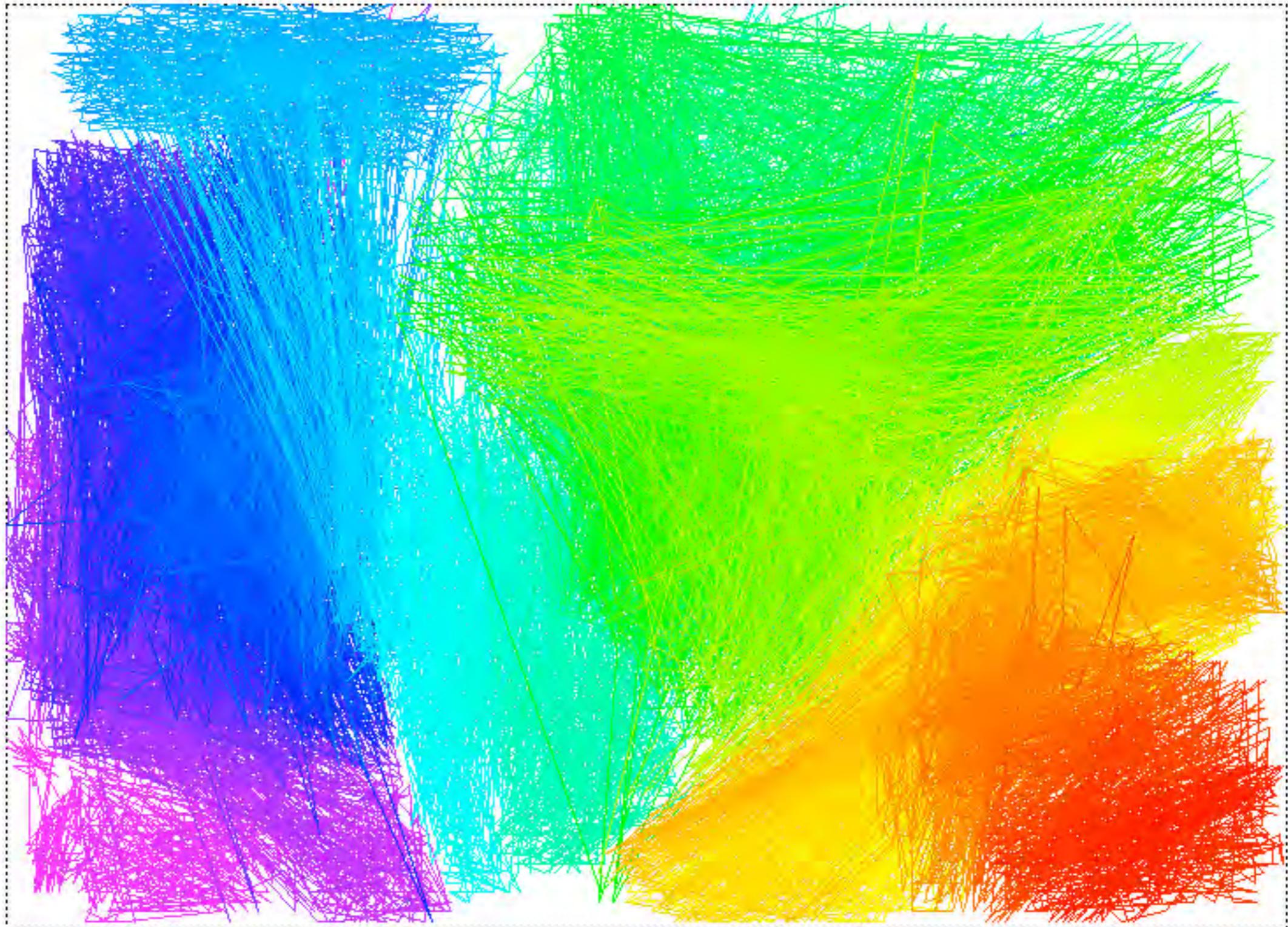
# Placement of IBM1

experiment2



# Routing Colors

OBS: This and other pictures will be presented at the DAC ART SHOW, Austin, Texas, June 6-9, 2016



IBM1

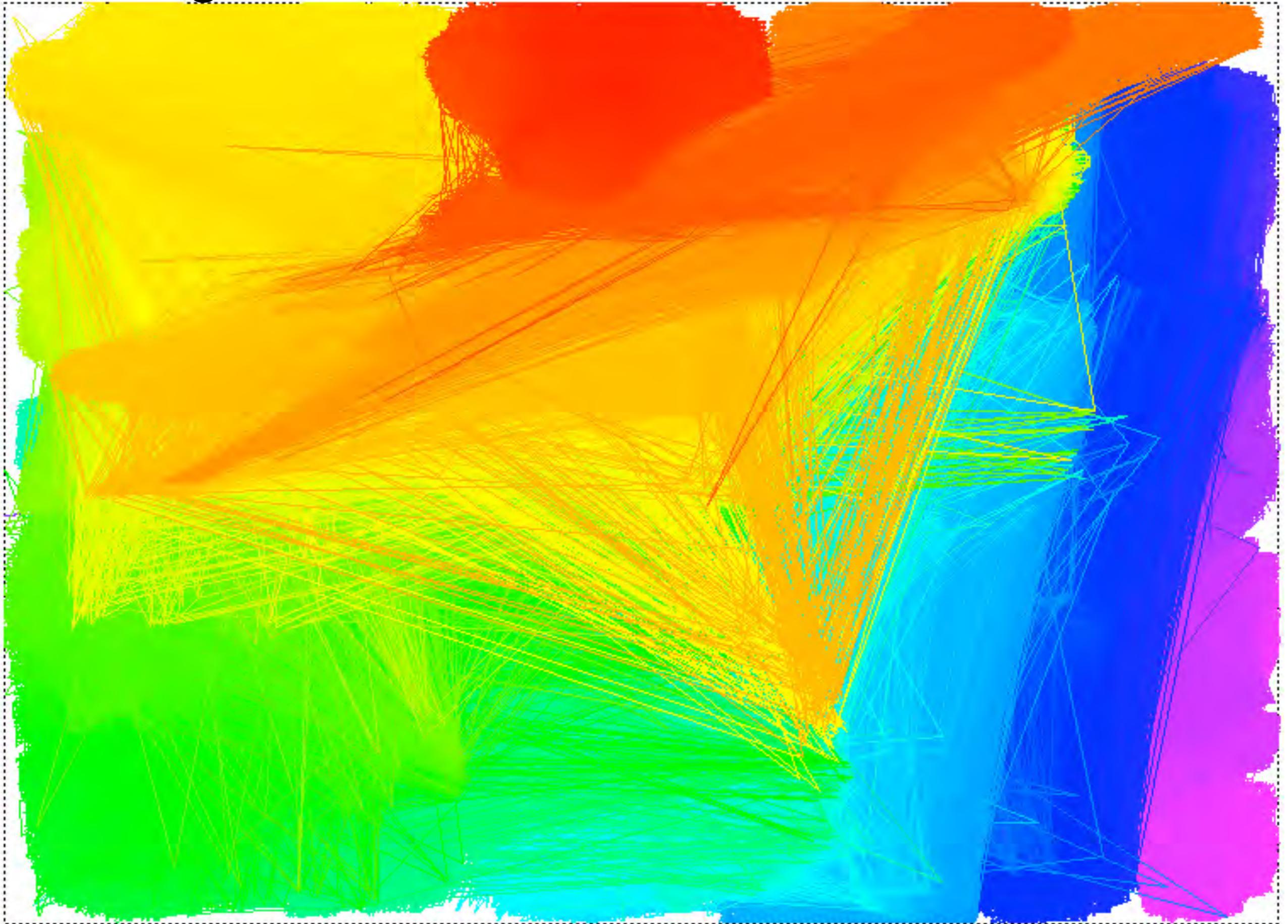
The logic cells were ordered according to the Fiedler Vector (autovector associated to the second smaller autovalue) of the connective matrix of the graph and a line was drawn between pairs of adjacent cells.

The **color of the line** is a gradient between the colour of the initial cell and the color of the sink cell.

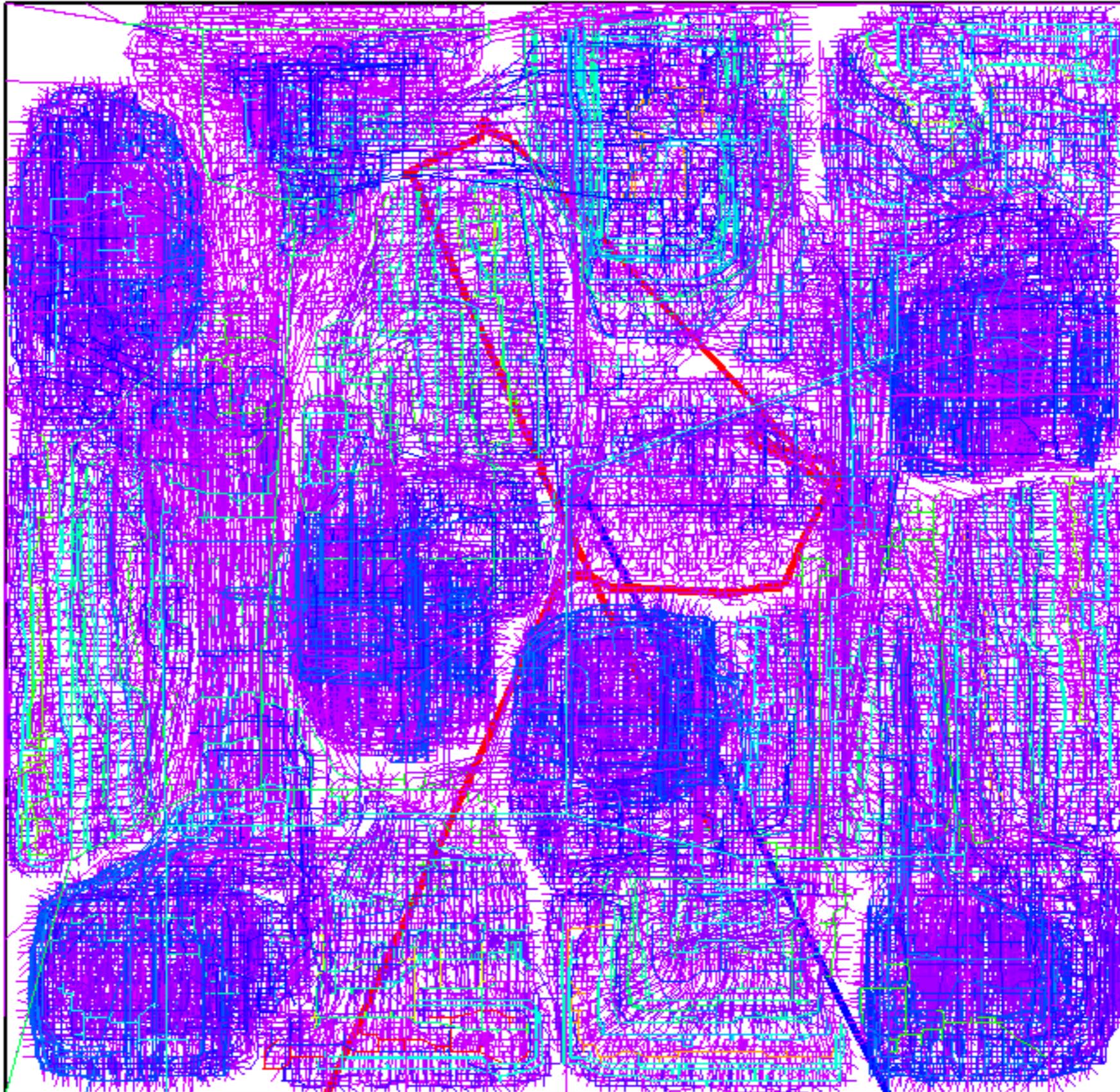
The **color of the cells** were obtained by mapping in a temperature map the value of the cell in the Fiedler Vector.

# Routing Colors

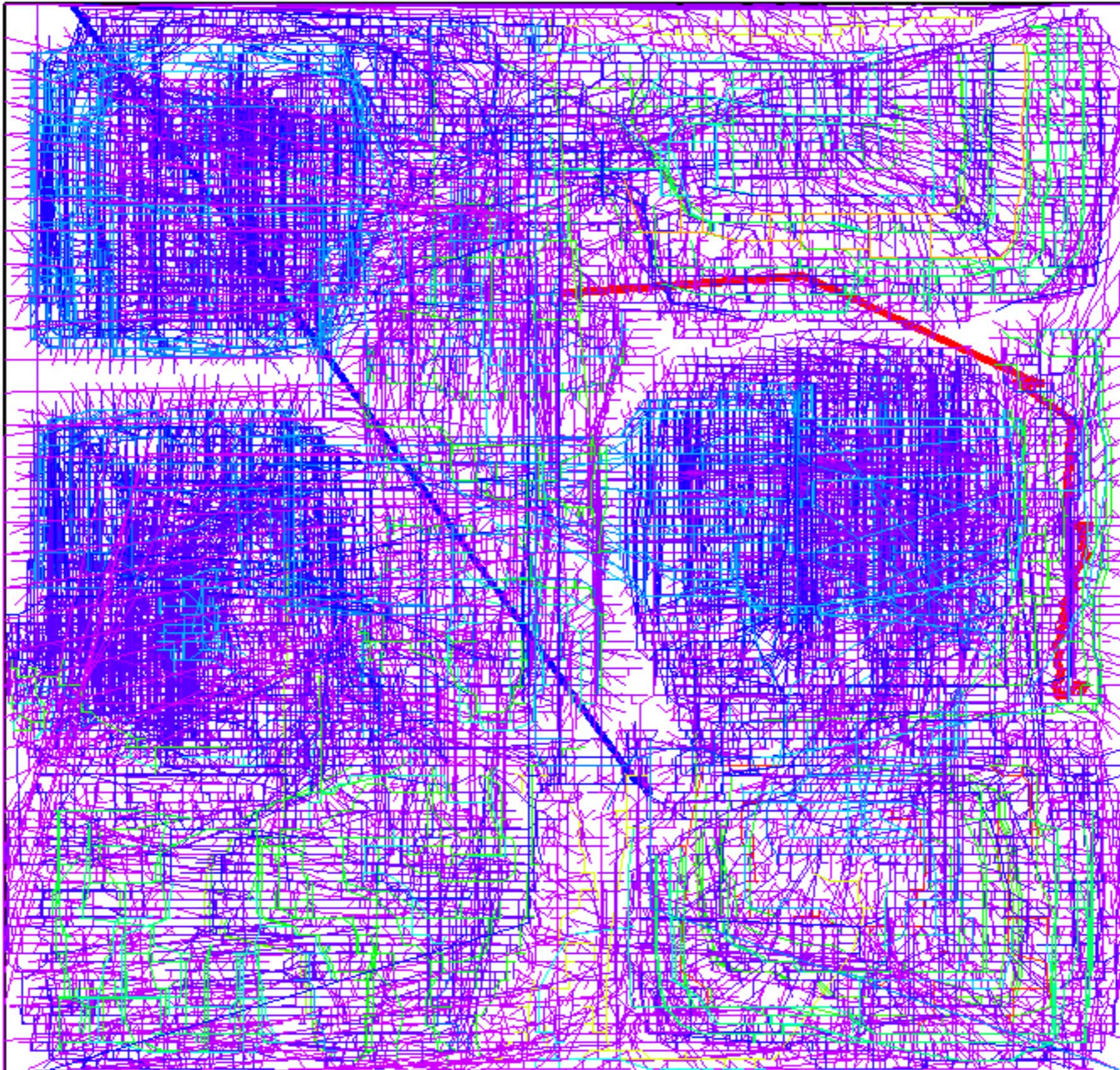
IBM18



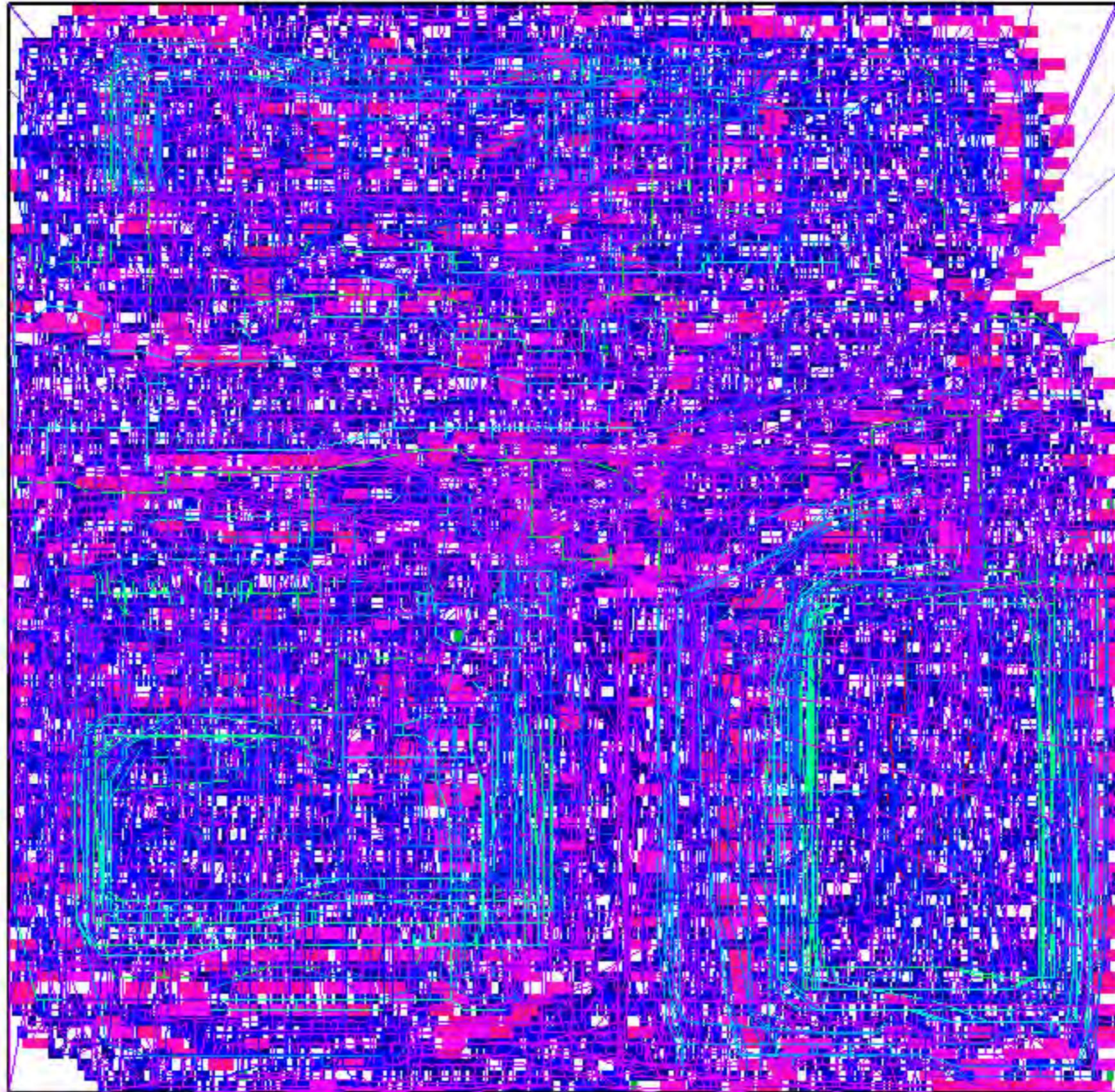
# Routing Estimation (b18)



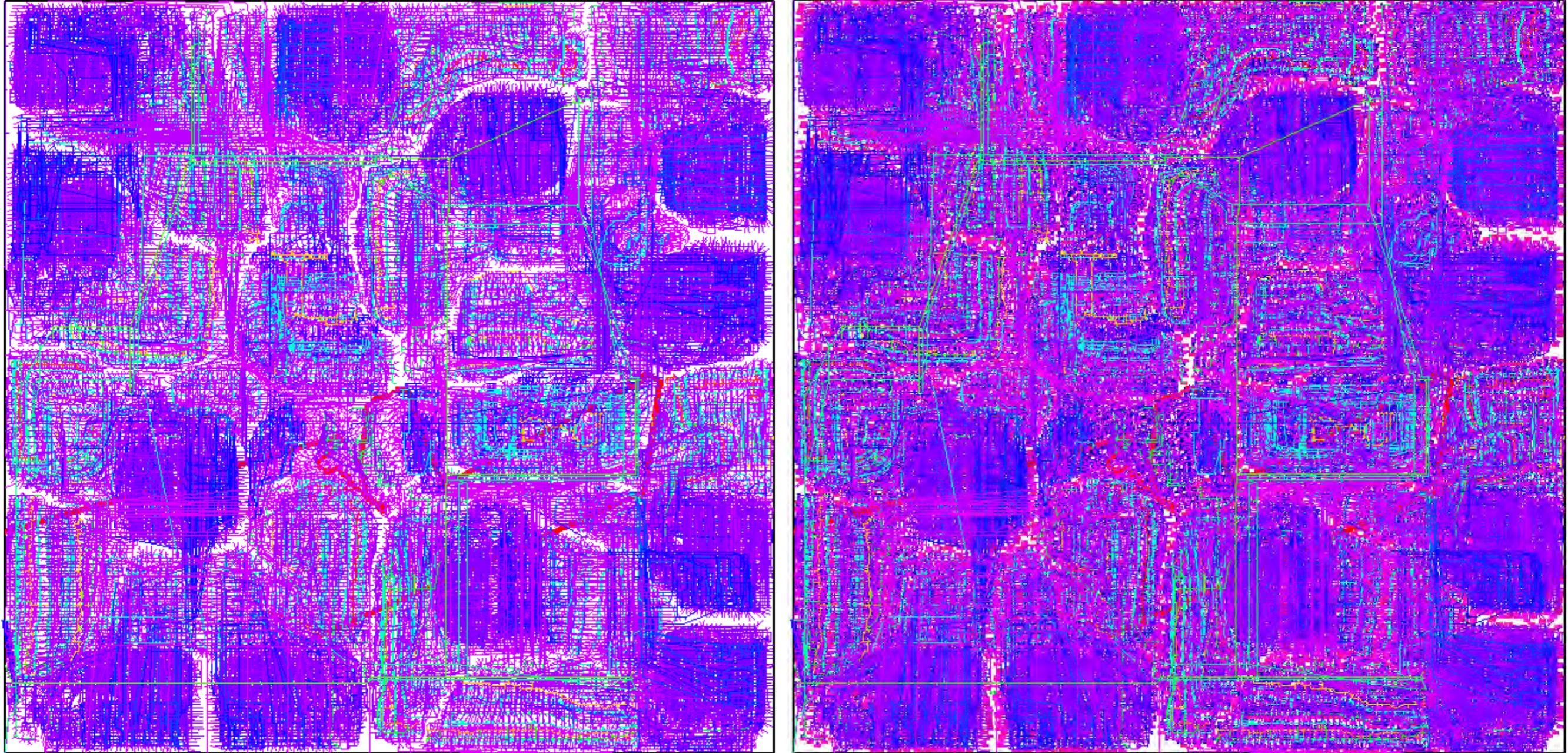
# Routing Estimation (b17)



# Routing Estimation (b22)

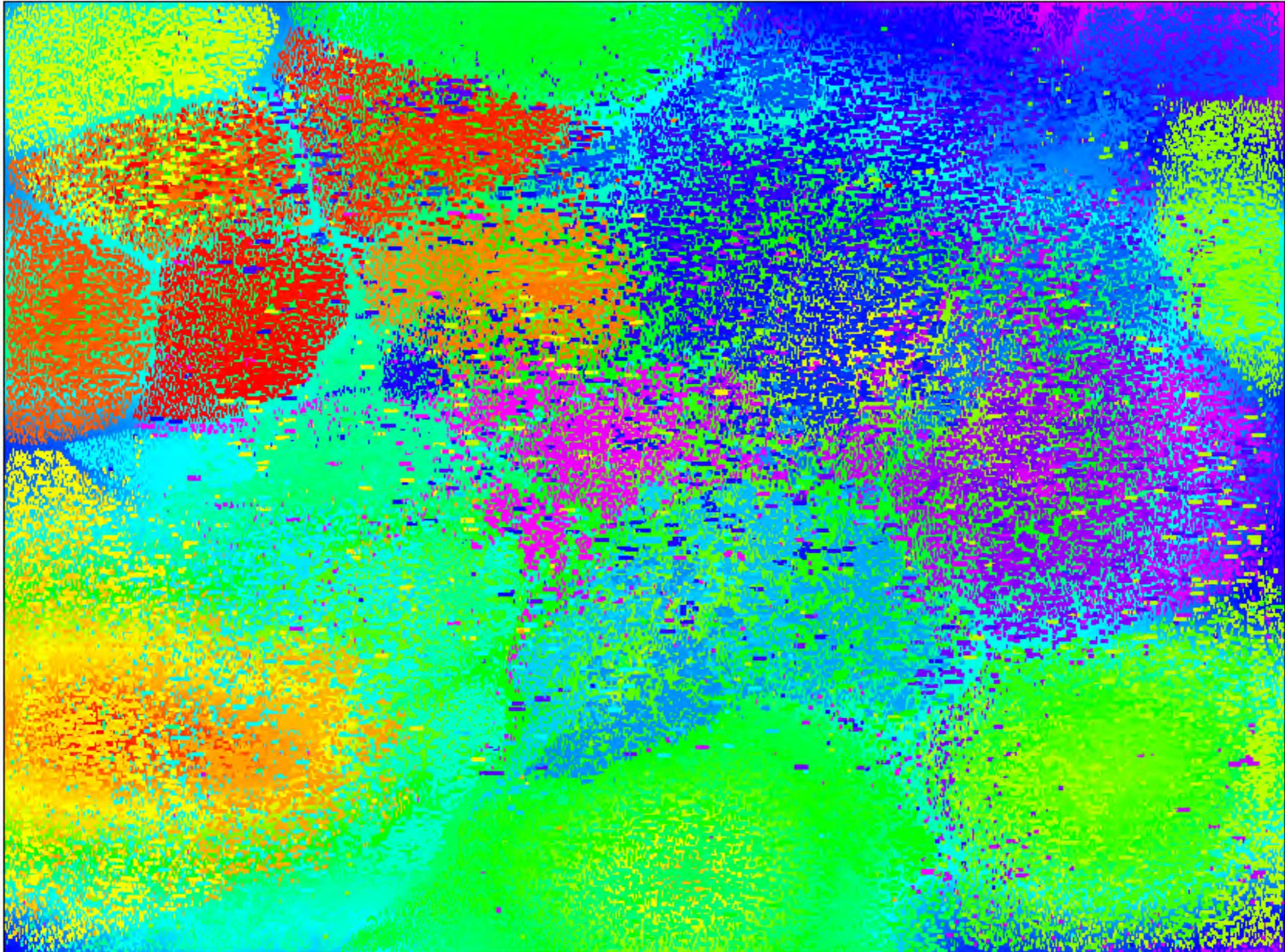


# Routing Estimation (b19)



# DAC ART SHOW 2016

Applying Poisson equation with a quadratic approach to standard cell placement.



# DAC 2017



cadence  
**Xcelium**  
Parallel Logic Simulation  
Industry's first parallel  
multi-core simulation

cadence  
**Palladium Z1**  
Enterprise Emulation Platform  
Fast emulation throughput for  
optimal global workload efficiency

cadence  
**Protium S1**  
FPGA-Based Prototyping Platform  
Reduce prototype bring-up from  
months to days

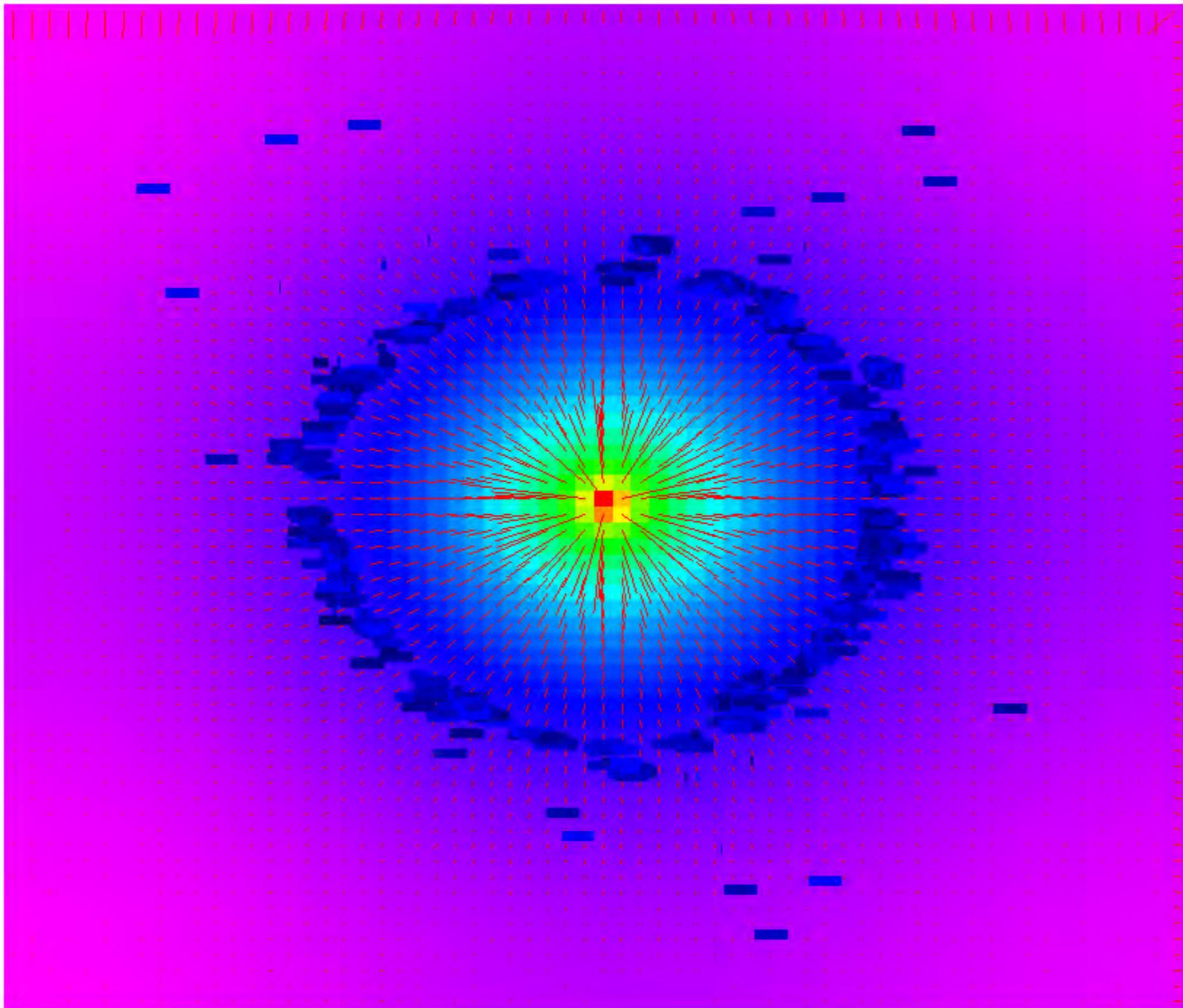
**Custom Compiler**  
Visually-Assisted Automation  
[www.customcompiler.info](http://www.customcompiler.info)  
Cut your FinFET Layout Tasks from Days to

**PEG**  
Verification  
Cloud-ready gate  
up to 10X DRC

REGENERATION

THANK YOU TO OUR

SPONSOR



Q |

Properties

Circuit

Name -

Width -

Height -

Density -

Interpolated Mode (Off)

Checkpoint

Step

Run

Report

Legalize

Update Steiner Trees

Update Timing

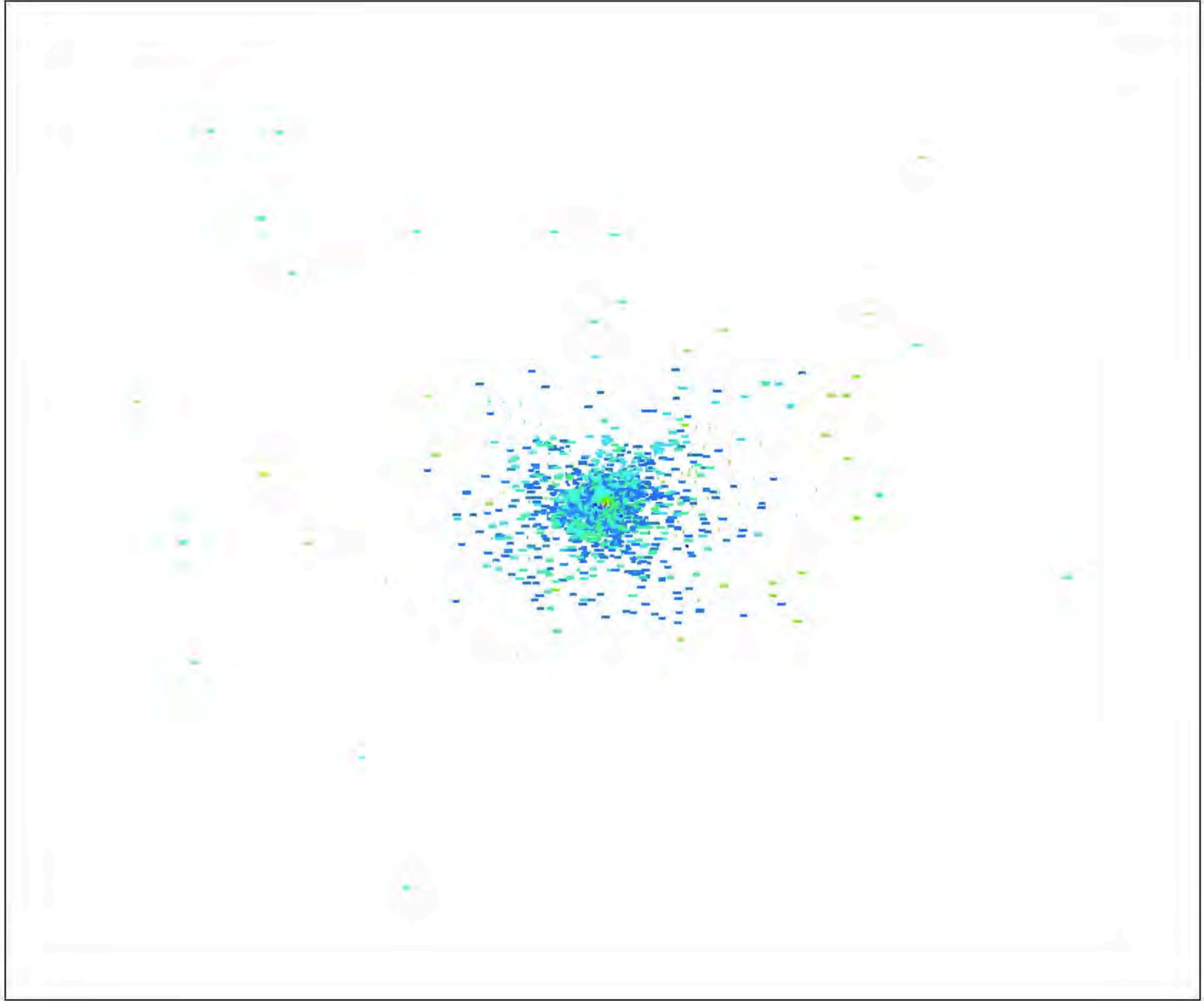
Guilherme

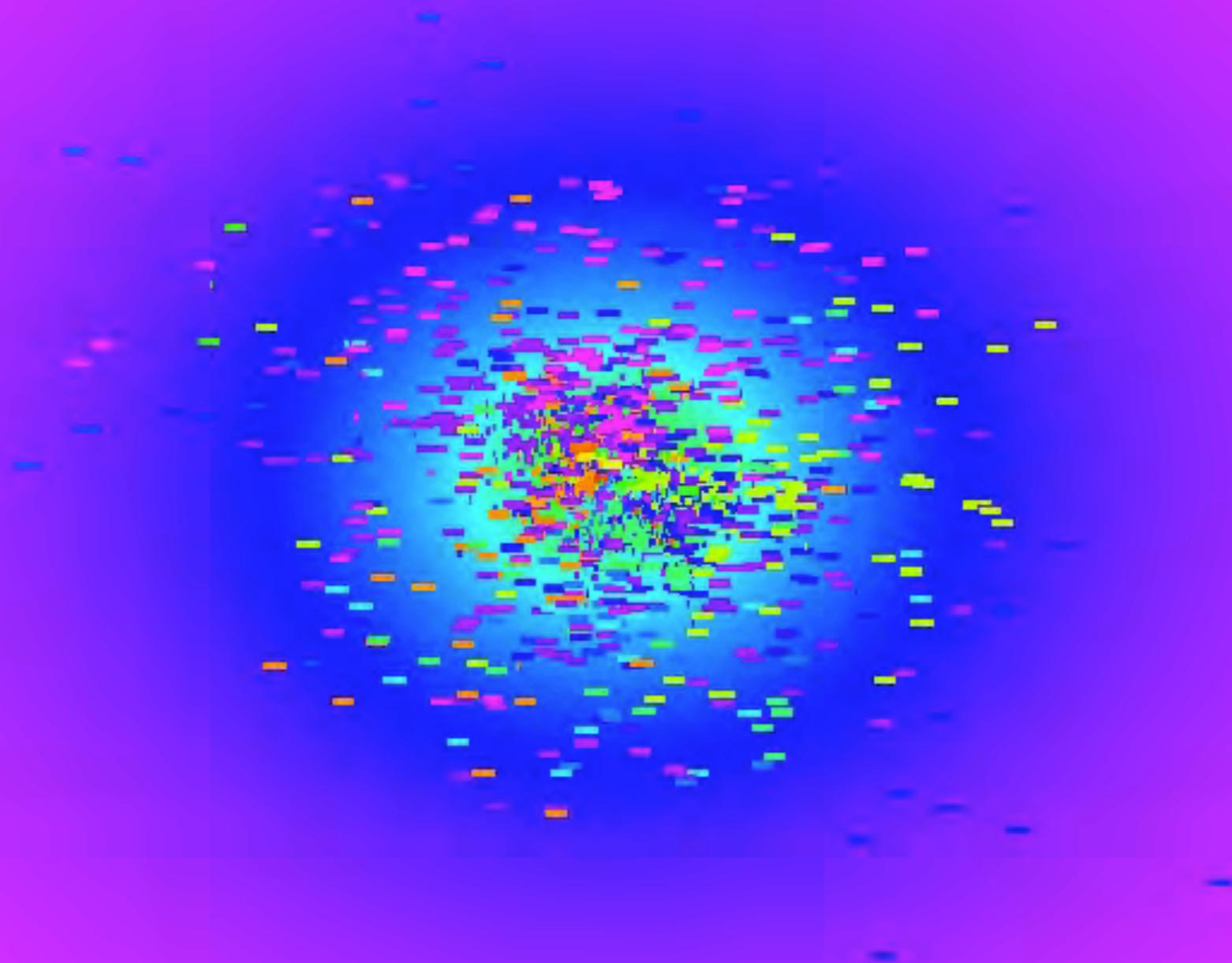
Jucemar

Mateus

Julia

Tiago





Placement

# ISPD - International Symposium on Physical Design Discrete Gate Sizing Contest 2012

organized by Intel

Second Place in one ranking (result metric)

First Place in the second ranking (that included running time)



Tiago Reimann, Guilherme Flach, Gracieli Posser  
Jozeanne Belomo, Marcelo Johann, Ricardo Reis

# ISPD - International Symposium on Physical Design Discrete Gate Sizing Contest 2013

organized by Intel

## First Place in the Primary Metric Ranking



# ICCAD Contest 2014

## First Prize

# Incremental Timing-Driven Placement

### Team:

Guilherme Flach, aluno de doutorado,  
Jucemar Monteiro, aluno de mestrado,  
Julia Puget, bolsista IC  
Mateus Fogaça, graduando na FURG,

### Advisors:

Marcelo Johann  
Ricardo Reis  
Paulo Butzen (FURG)



# ICCAD Contest 2015

## Second Place

## Incremental Timing-Driven Placement

### Team:

Guilherme Flach, PhD student  
Jucemar Monteiro, PhD student  
Mateus Fogaça, PhD student  
Tiago Reimann, PhD student



### Advisors:

Marcelo Johann  
Ricardo Reis



# Conclusions

The use of visualizations tools is more and more important to improve:

Algorithm behaviours

Evaluation of the solution quality

Design debug

Design improvement

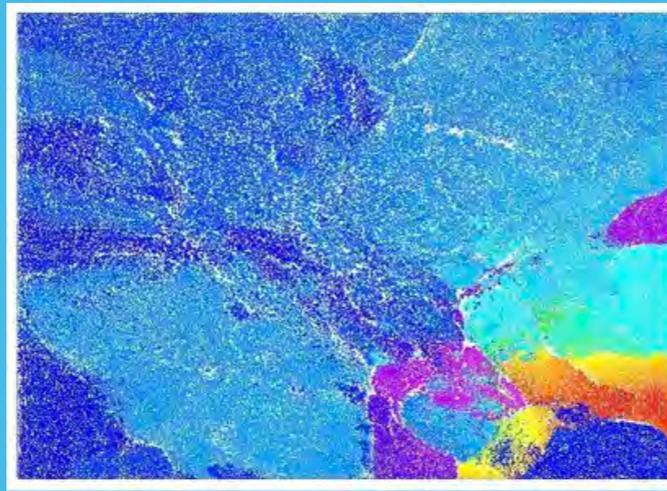
IEEE CASS Seasonal School on

# Physical Design Automation

Porto Alegre, Brazil

July 31 to August 5, 2017

[www.inf.ufrgs.br/cass/pda/](http://www.inf.ufrgs.br/cass/pda/)



The 2017 Seasonal School on Physical Design Automation aims to offer a set of talks on key topics of physical design automation of integrated circuits in modern and upcoming technologies. It should represent current and future challenges that are faced by industry and academia for the implementation of ever more complex circuits and systems. We want to promote discussion on hot topics and cover fundamental algorithms and computational methods in the area, so that the attendance can leverage their comprehension and capabilities, while also attracting new students and researchers to the right problems. The courses will be given by prominent international researchers with extensive expertise in their fields. Associated to the school, a book will be organized and published by an internacional publisher.

The School's technical program will include 8 courses of 2h40min each, divided into two parts of 1h20min each, with a coffee break. There will be a panel each day to involve participants into discussions related to the subjects covered. In the afternoon coffee break, there will be a poster sessions related to the school topics. The corresponding call for posters is available in the webpage.

## THE MAIN TOPICS TO BE COVERED BY THE SCHOOL WILL INCLUDE:

- Global and Detailed placement
- Gate sizing
- Routing and routability
- Tools for 3D architectures
- Layout manufacturability
- Clock routing buffer/wire sizing
- Machine Learning for EDA
- Layout Design Automation

Some of the speakers are:

- Andrew Kahng, UCSD, USA
- William Swartz, TimberWolf Systems and UT Dallas, USA
- Laleh Behjat, Univ. Calgary, Canada
- Patrick Madden - SUNY Binghamton, USA
- Ulrich Brenner - University of Bonn, Germany
- Evangeline Young - CUHK, Hong Kong
- Mark Po-Hung Lin - NCCU, Taiwan
- Patrick Groeneveld, Formerly Synopsys, USA

General Chair :Ricardo Reis, UFRGS, Brazil

Program Chairs

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Poster Session Chair: Jucemar Monteiro, UFRGS

Local Organization Chair

Mateus Fogaça, UFRGS  
Jody Matos, UFRGS

IEEE CASS Liaison: Ricardo Reis, UFRGS, Brazil

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- Analog and Digital Signal Processing
- Nanoelectronics and Gigascale Systems
- Cellular Neural Networks and Array Computing
- Neural Systems and Applications
- Circuits and Systems for Communications
- Nonlinear Circuits and Systems
- Graph Theory and Computing
- Electronic Design Automation
- Power Systems and Power Electronic Circuits
- RF Circuits and Systems
- Intelligent Sensor Systems
- Visual Signal Processing and Communications
- Multimedia Systems and Applications
- Life Science Systems and Applications
- Biomedical Circuits and Systems
- VLSI Systems and Applications
- Systems on Chip
- Electronic Testing
- Fault Tolerant Circuits



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**Call for Papers, Tutorials and Special Sessions:**

Tutorial proposals: October 6, 2017  
Special Session Proposal: October 6, 2017  
Paper Submission: October 20, 2017  
Notification of acceptance: November 21, 2017  
Camera-ready: December 20, 2017

<http://www-elec.inaoep.mx/~LASCAS18>

The proceedings will be published by IEEE Xplore, and extended versions of a selection of the best papers will be invited to submit to a Special Issue of the IEEE TCAS I, Transactions on Circuits and Systems I, published by IEEE.

LASCAS2018 will be colocated with IBERCHIP 2018 and PRIME2018.



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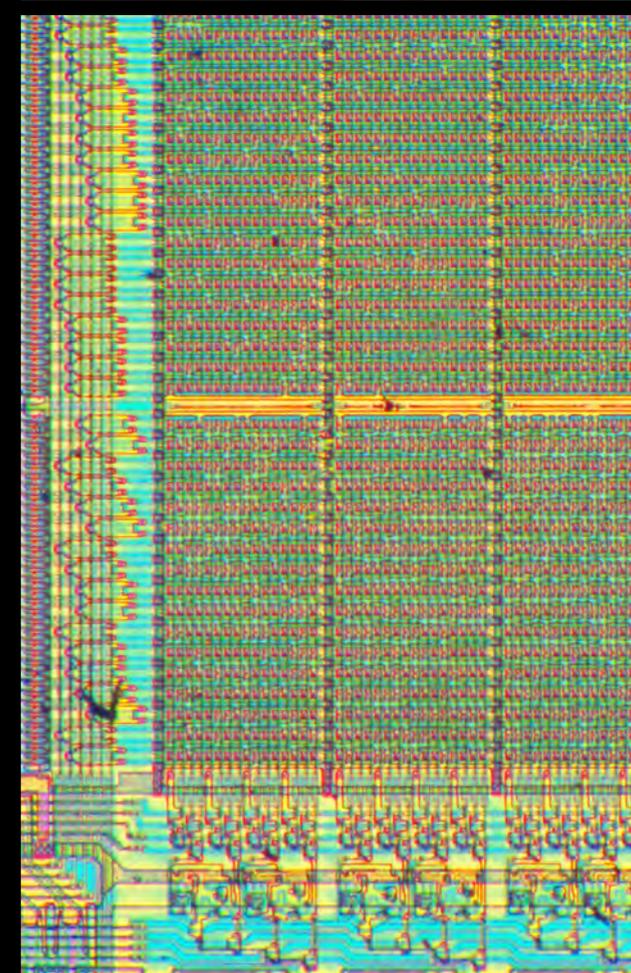
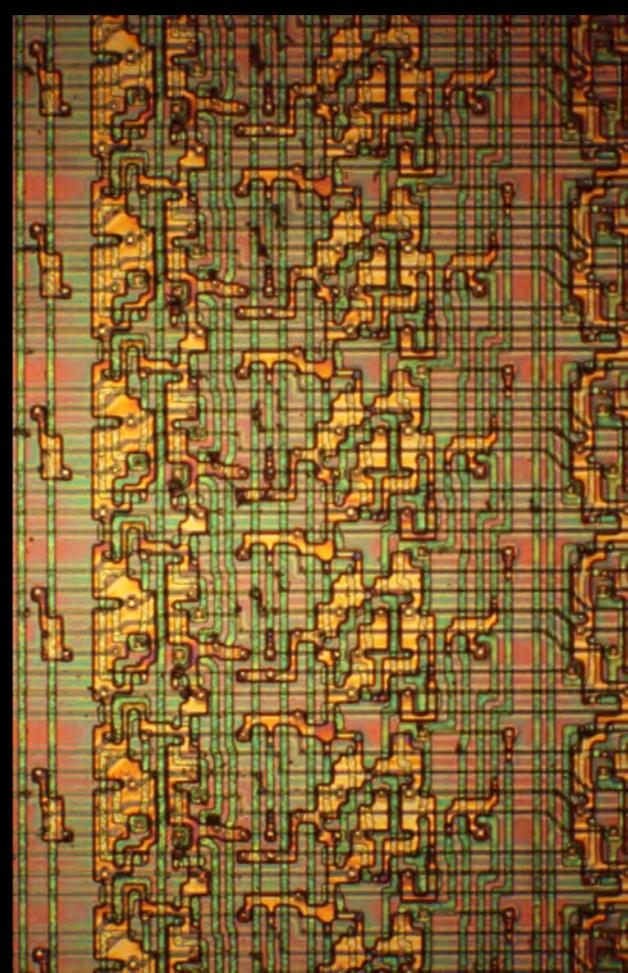
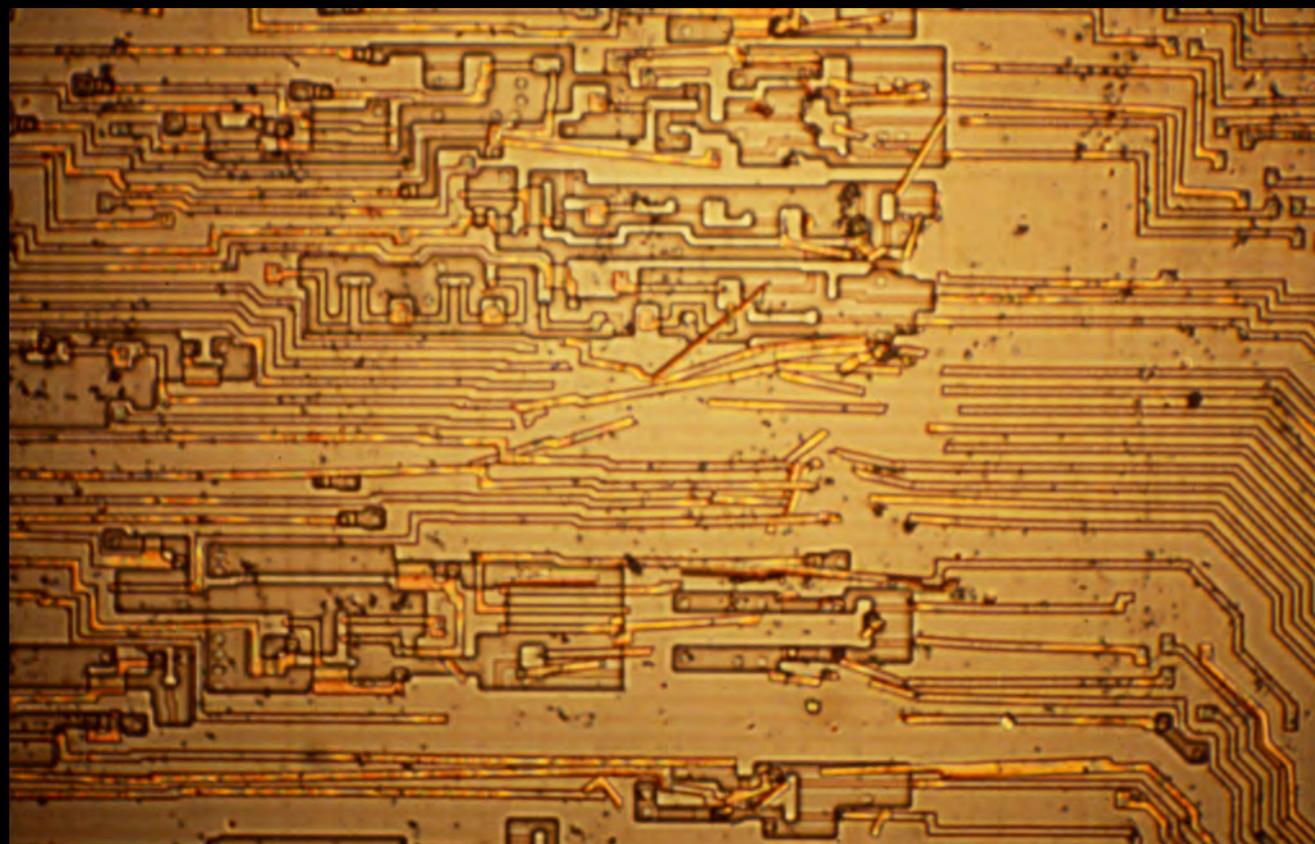
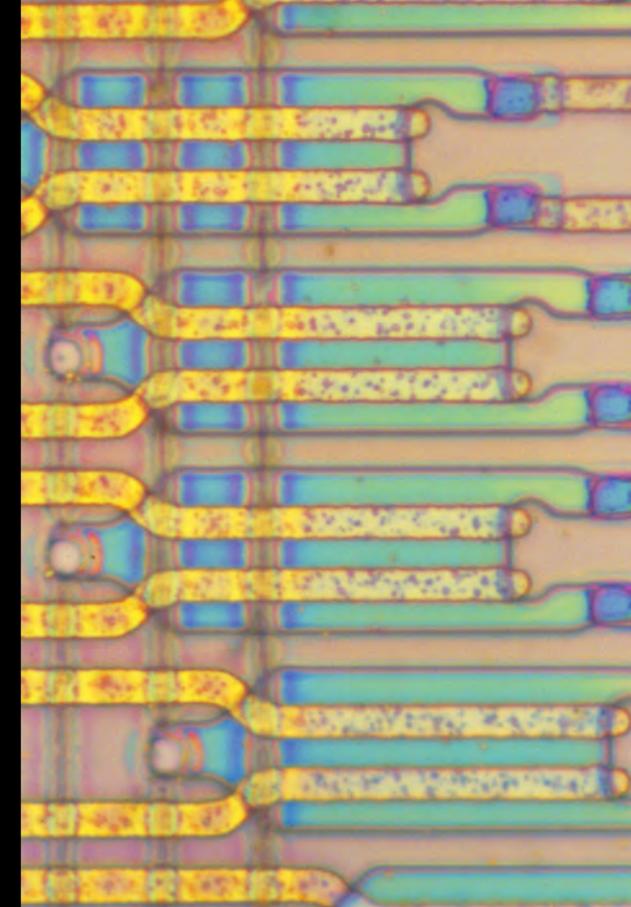
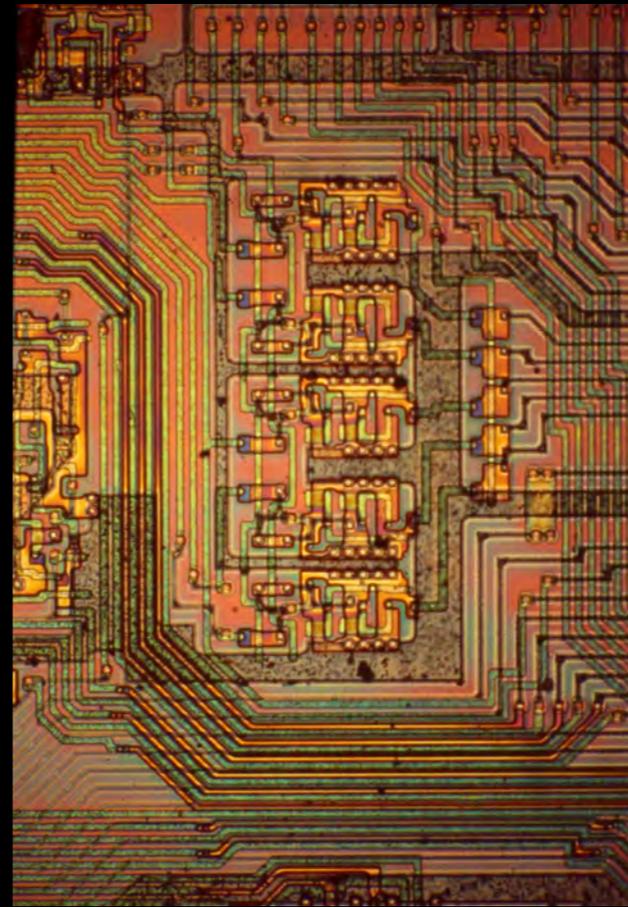
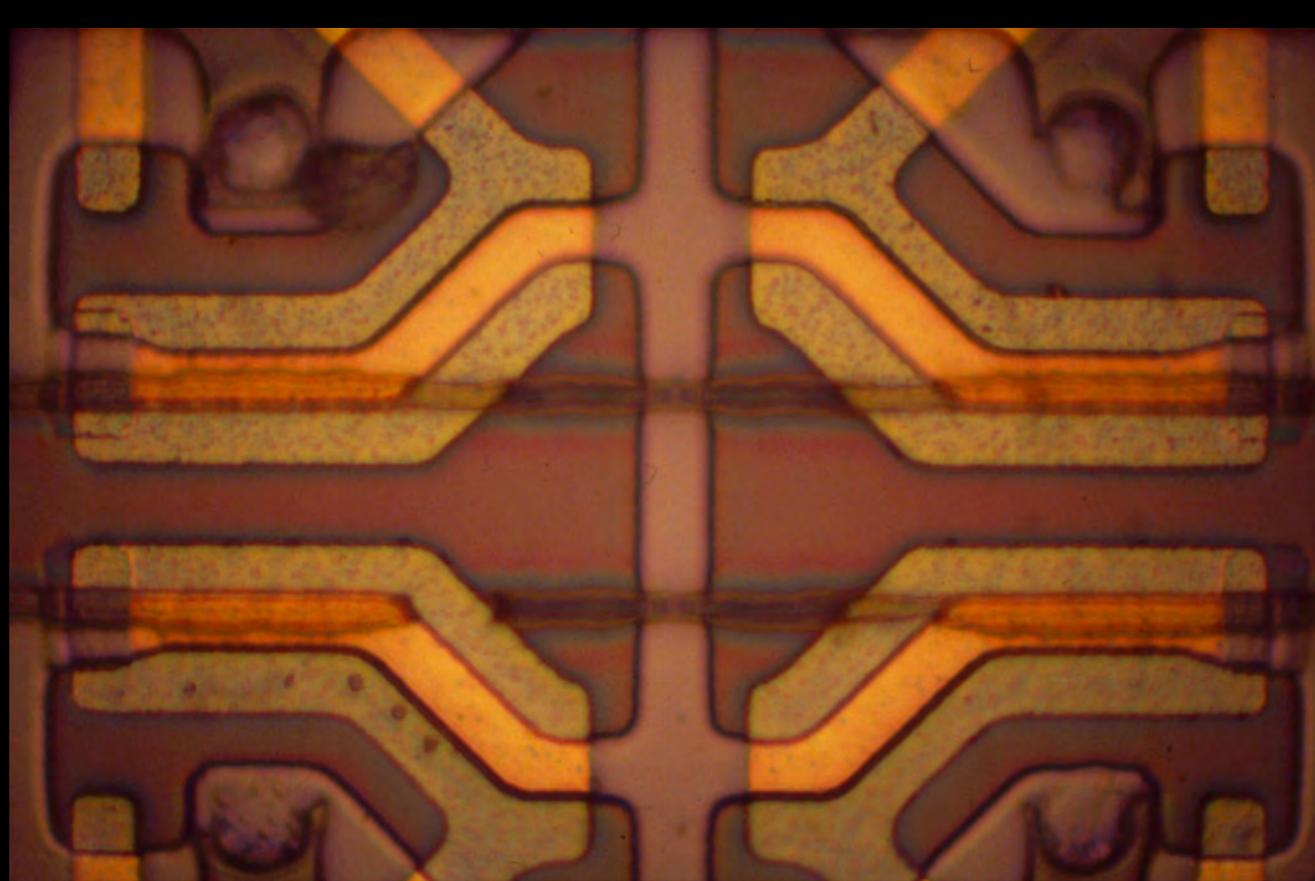
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